



Topical Workshop on Electronics for Particle Physics

2 - 6 September, 2019 - Santiago De Compostela - Spain

# Electronics readout for the CGEM - Inner Tracker: TIGER ASIC and electronics chain

Alberto Bortone

on behalf of the BESIII Italian Collaboration

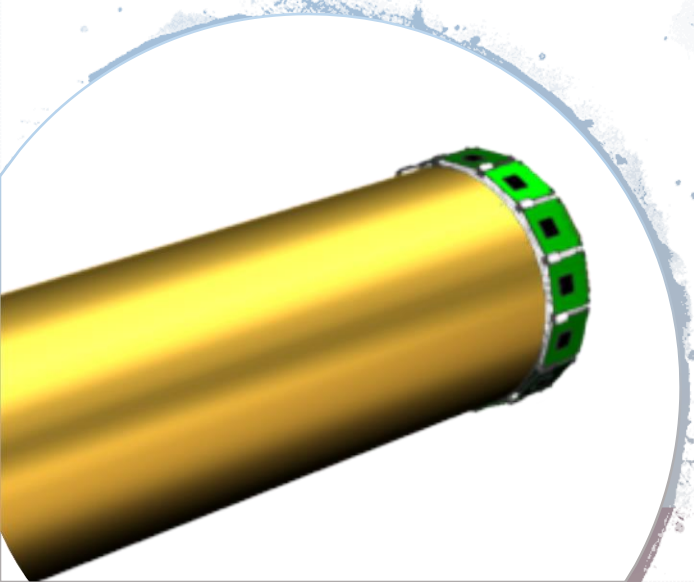
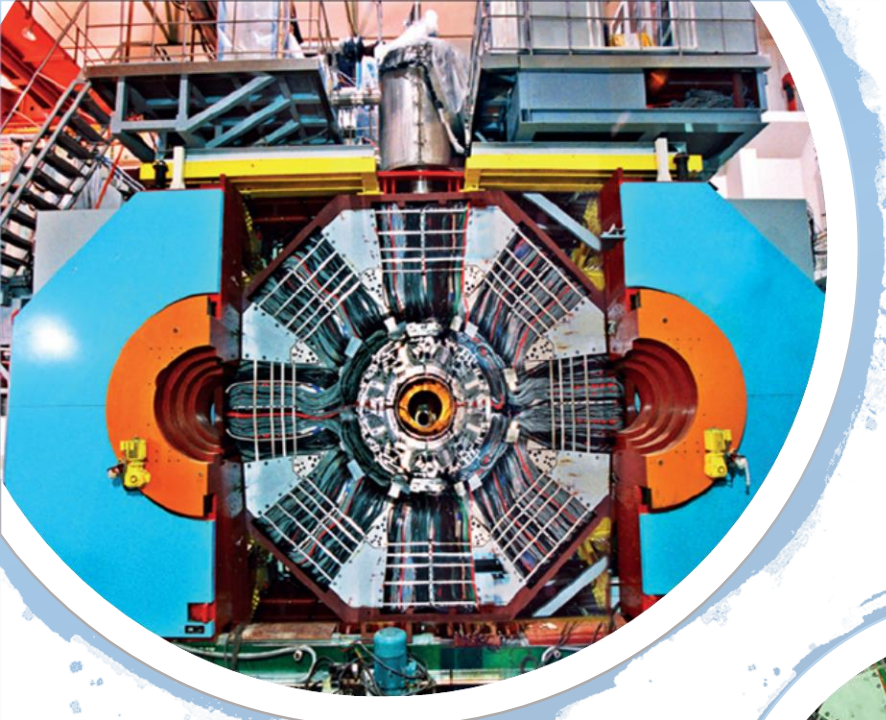


UNIVERSITÀ  
DEGLI STUDI  
DI TORINO



# Outline

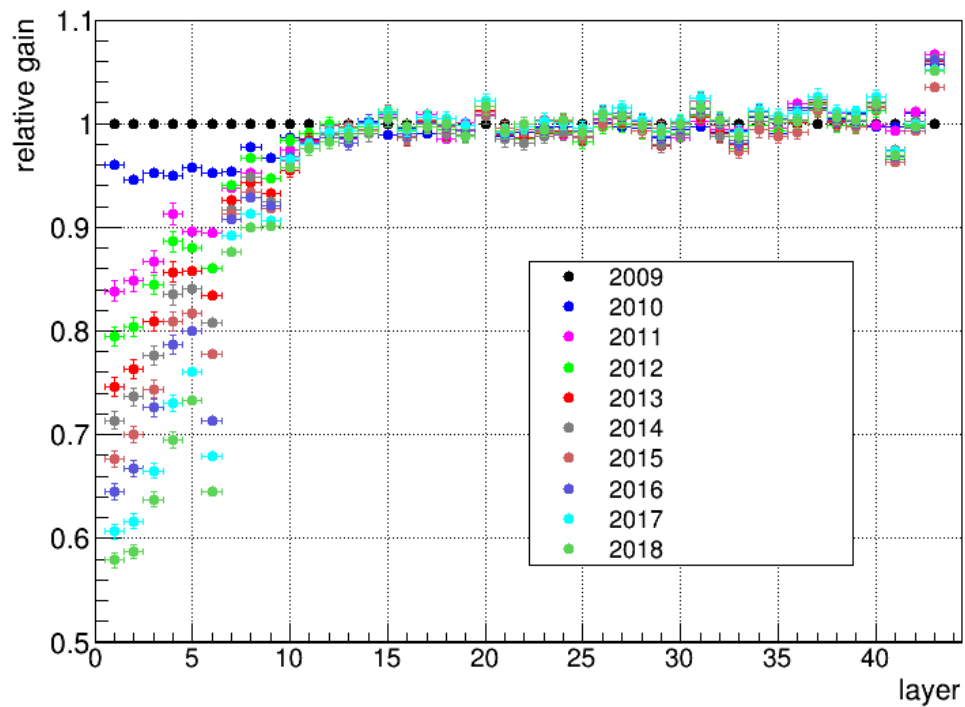
- BESIII and CGEM-IT
- TIGER ASIC
  - Design
  - On silicon characterization
- Off detector electronics
- Detector integration



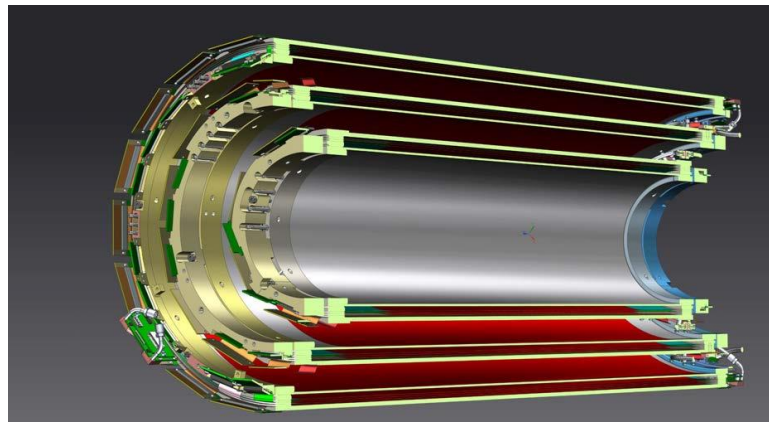
# Introduction: BESIII and CGEM-IT



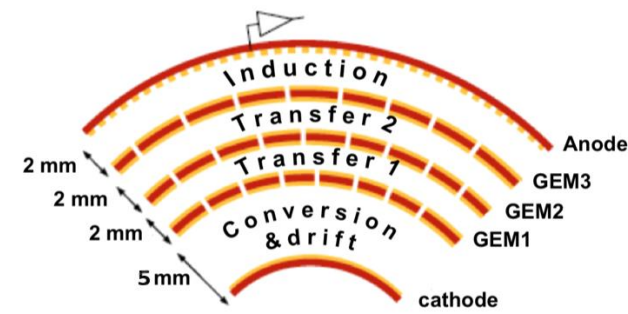
# Cylindrical Gas Electron Multiplier Inner Tracker



Loss of gain in current MDC



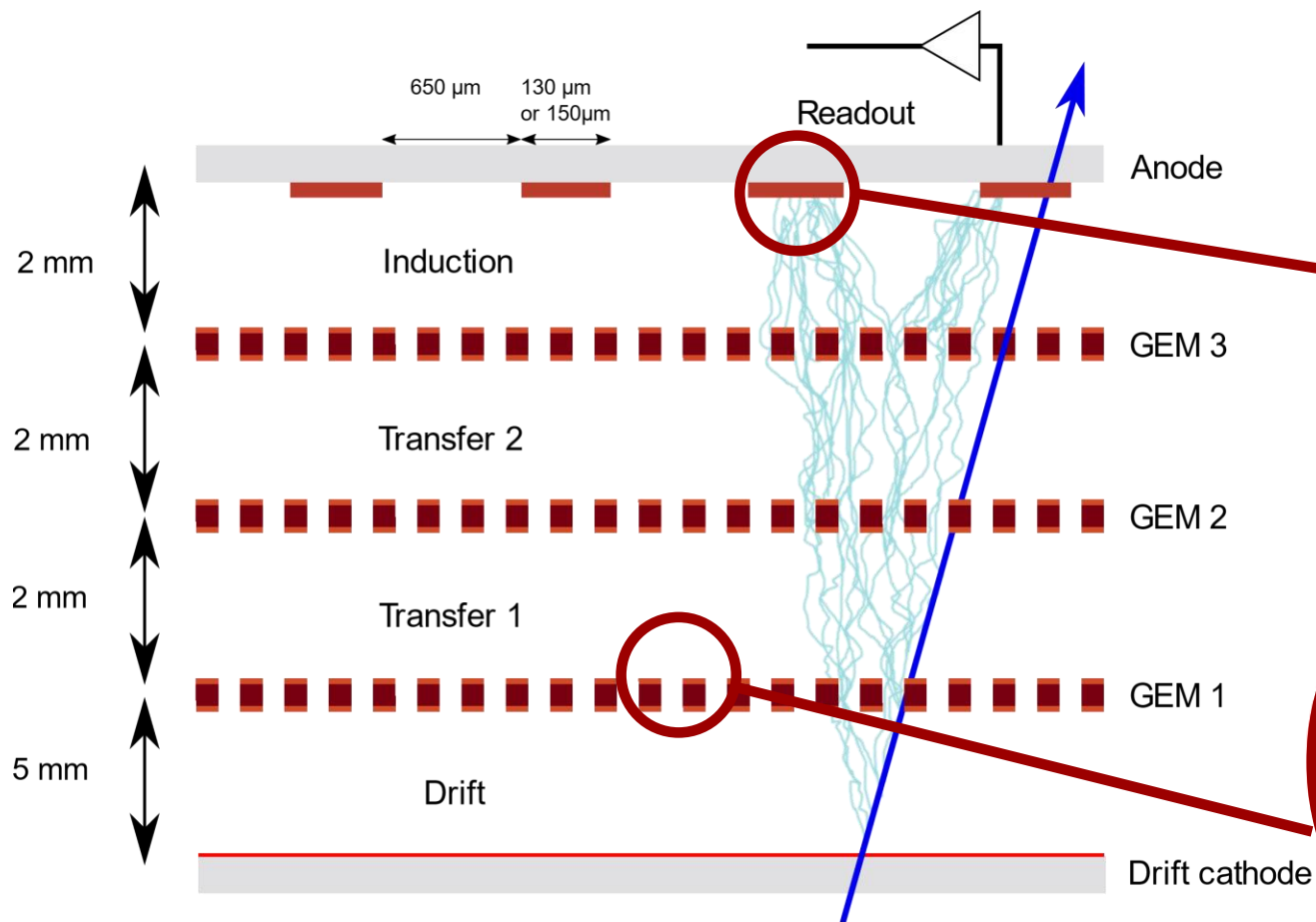
CGEM CAD model



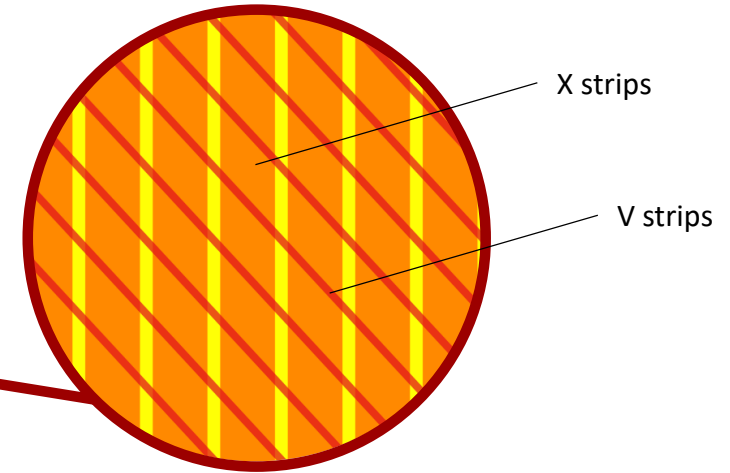
Single layer internal layout

- Detector features:**
- Radial resolution  $< 130 \mu\text{m}$
  - Resolution along the beam direction  $< 500 \mu\text{m}$
  - Momentum resolution  $\sigma_{p_t}/p_t \sim 0.5\%$
  - Time resolution about 5 ns
  - Material budget  $X_0 \sim 0.5\%$  for each layer
  - High rate capabilities ( $10\text{kHz}/\text{cm}^2$ )

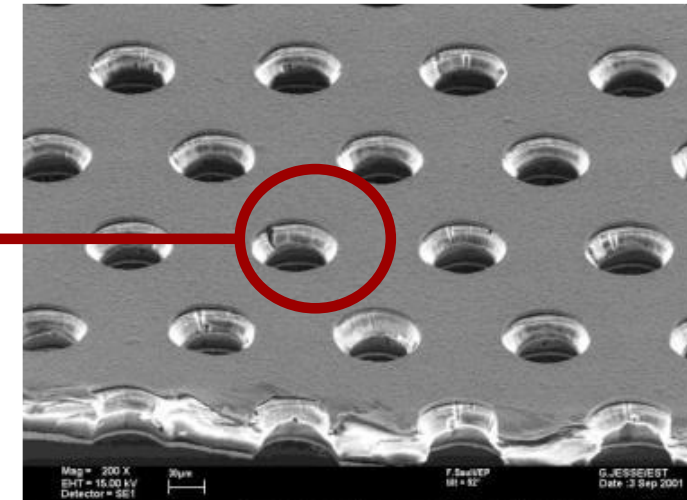
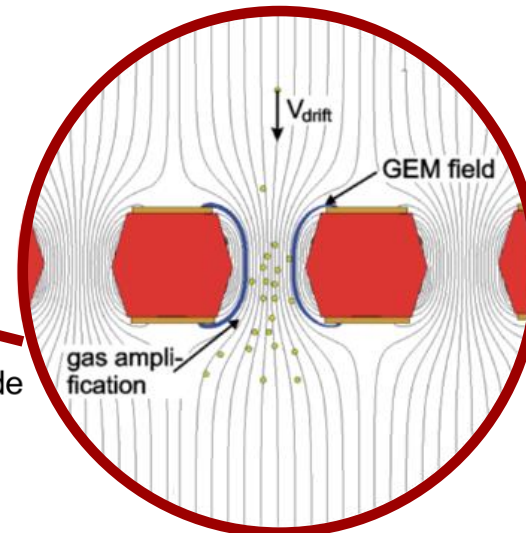
# GEM working principles



Anode strip structure



Holes structure

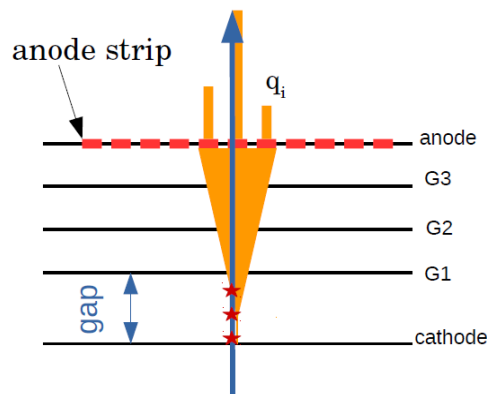


Ref. Fabio Sauli "The gas electron multiplier ( GEM )" in: Nuclear Inst. and Methods in Physics Research, A 805 (2016), pp. 2–24.

# Analog readout

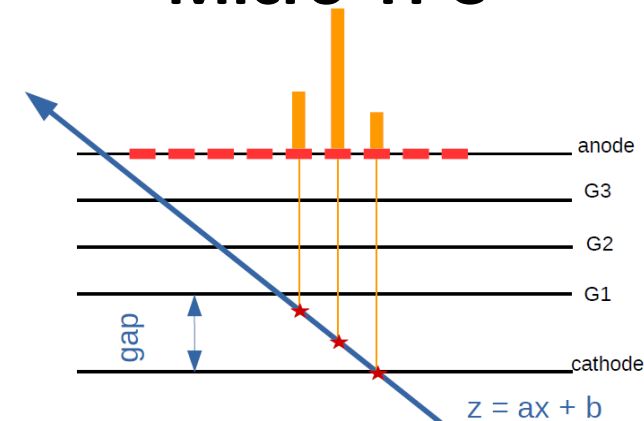
- Charge centroid and  $\mu$ -TPC algorithms
- 130  $\mu\text{m}$  spatial resolution with strip pitch of 650  $\mu\text{m}$
- Total number of channels  $\sim 10\,000$  (vs 25000 with binary readout to obtain similar resolution)
- Apply threshold on collected charge to cut noise-induced events

## Charge centroid



- Weighted average position from fired strips
- Improve spatial resolution vs digital readout (constrained to the strip pitch)

## Micro-TPC



- Known the drift velocity, use time information to project the signal origin on the Z axis
- Reconstruct the particle track from these coordinates
- Improve the spatial resolution for tilted tracks and in magnetic fields

Ref. Lia Lavezzi et al. "The new cylindrical GEM inner tracker of BESIII" in: Int.J.Mod.Phys.Conf.Ser. 46 (2018), DOI: 10.1142/S2010194518600777

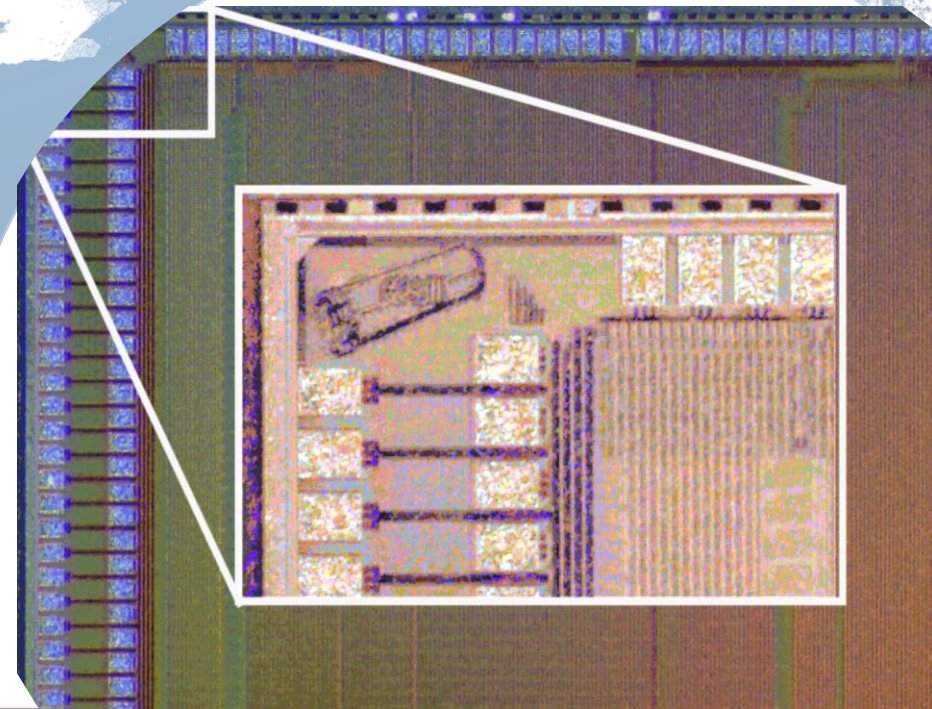
# TIGER

## Design:

- INFN-Torino
- LIP-Lisboa
- PETSYS-Lisboa
- IHEP Beijing

## Test ancillaries:

- INFN-Torino

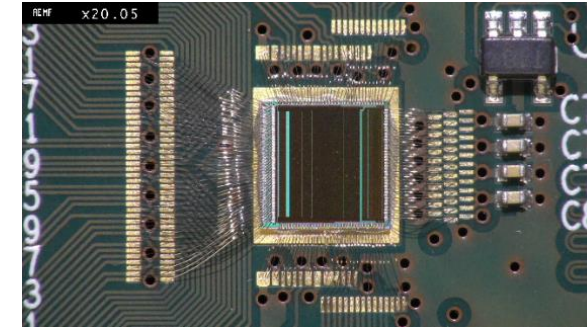
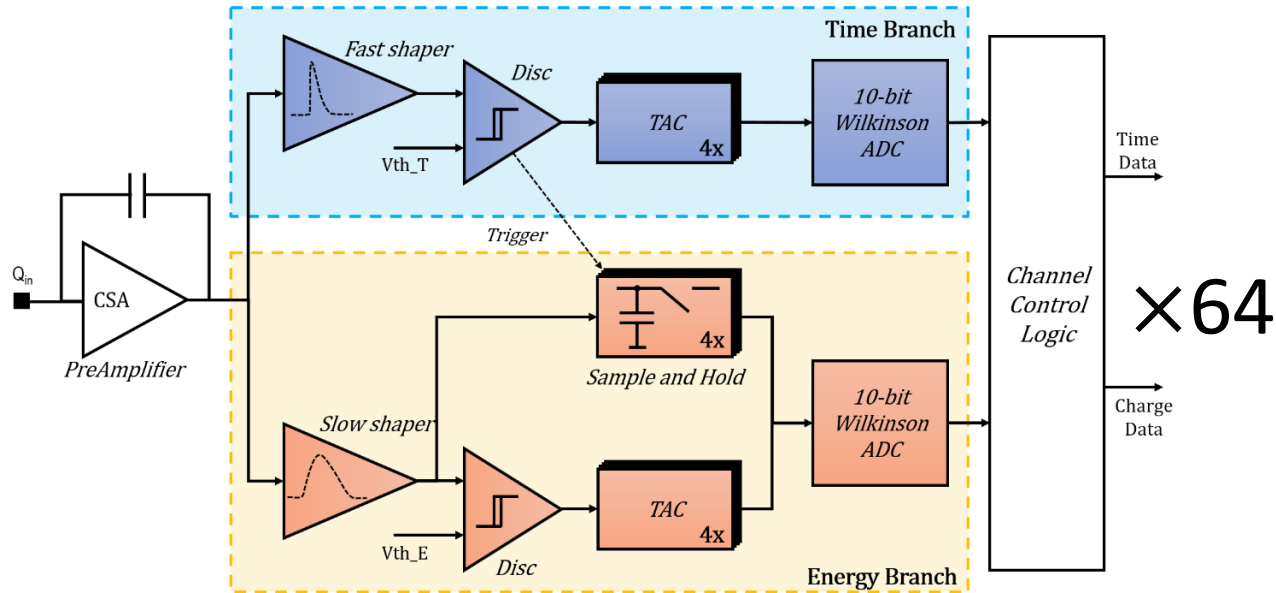




# TIGER ASIC

Torino Integrated Gem Electronics Readout

Font end architecture



TIGER bonded on PCB



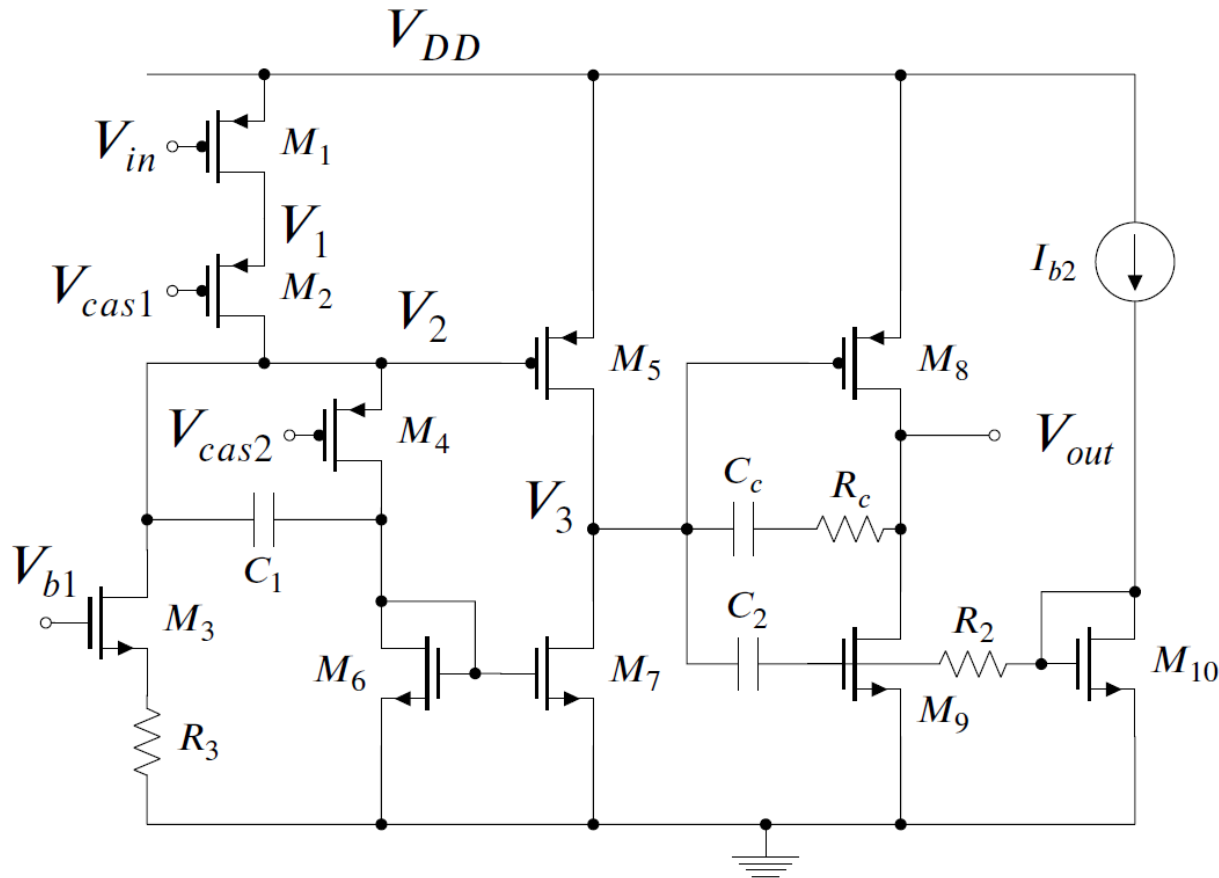
Front end board (FEB)

## Chip features:

- 64 channels
- Power consumption < 12 mW/channel
- Sustained event rate 100 kHz
- Input dynamic range up to 50 fC
- Time resolution < 5 ns

- ENC < 2000 e<sup>-</sup> rms with 100 pF input capacitance
- Analog read out providing charge and time measurement
- Digital logic protected from single event upset (SEU)
- Tunable internal test pulse generator
- 110 nm technology

# Charge Sensitive Amplifier



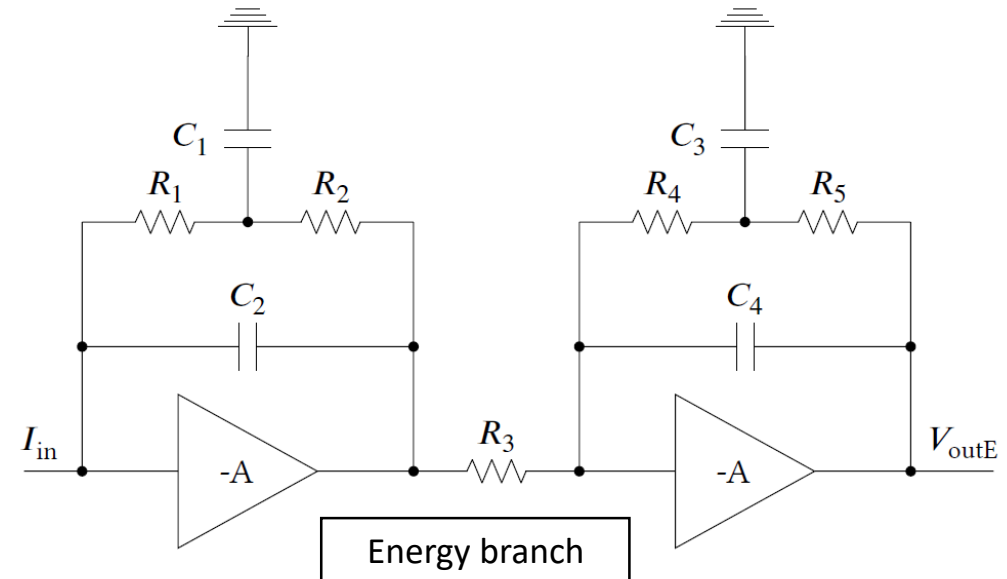
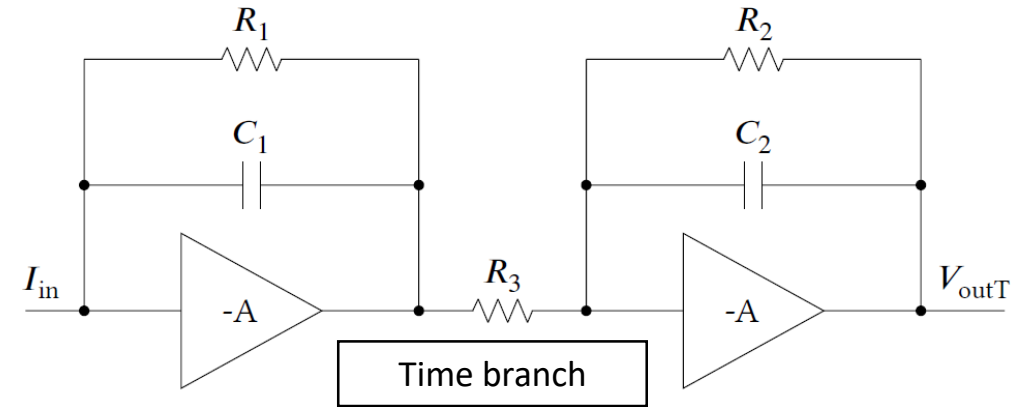
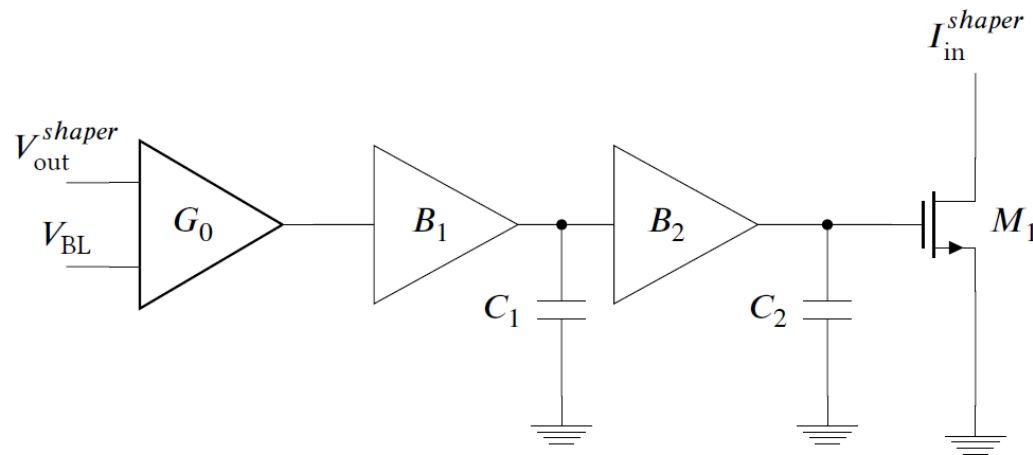
## Three stage cascoded common source amplifier

- ENC target  $< 2000 e^-$  @  $C_{in} = 100 \text{ pF}$
- $Q_{in} = 2 - 50 \text{ fC}$
- PMOS input transistor to reduce  $1/f$  noise
- $g_{m1} \approx 80 \text{ mS}$  (3.6 mA bias current)

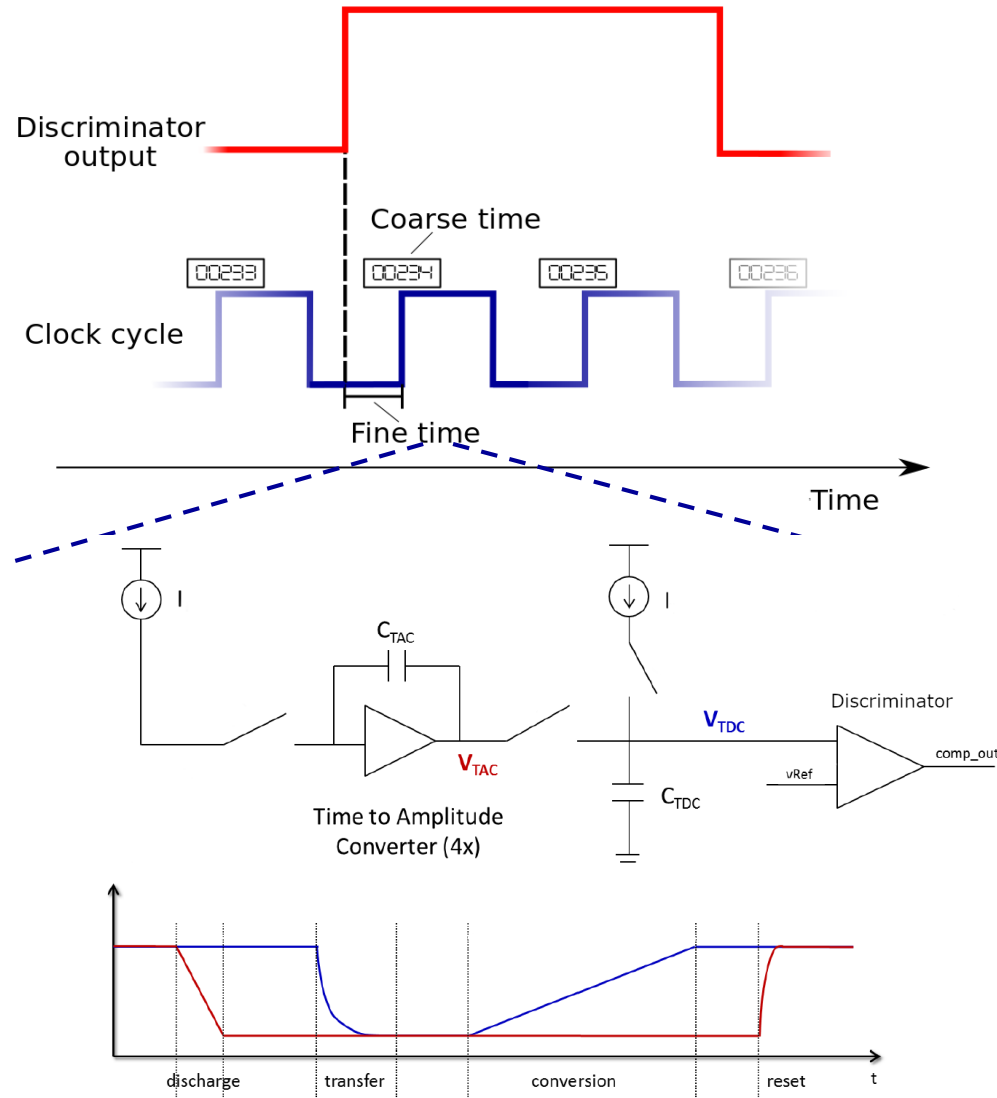
Ref. G. De Geronimo "An ASIC for micropattern detectors" in: *IEEE Trans. Nucl. Sci.*, 60:2314-2321.2013

# Shaping

- Peaking time defined by feedback loop RC
  - **Time-branch**: 60 ns peaking time for low-jitter timing measurement
  - **Energy-branch**: 170 ns peaking time for signal-to-noise ratio optimization
- **Baseline holder** to lock the shapers output DC to an external reference value ( $V_{BL} = 350$  mV)



# Time measurement



## Three accuracy levels (@160 MHz)

### Frame-word

Clock counter cycles roll-over  
204.8  $\mu$ s time resolution

### Coarse time

Hit clock cycle (16 bit counter)  
6.25 ns time resolution

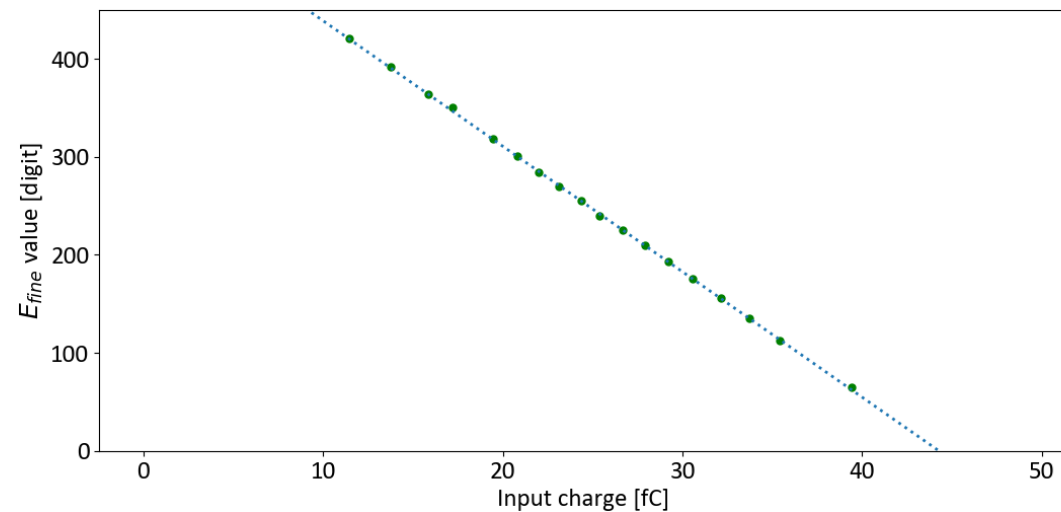
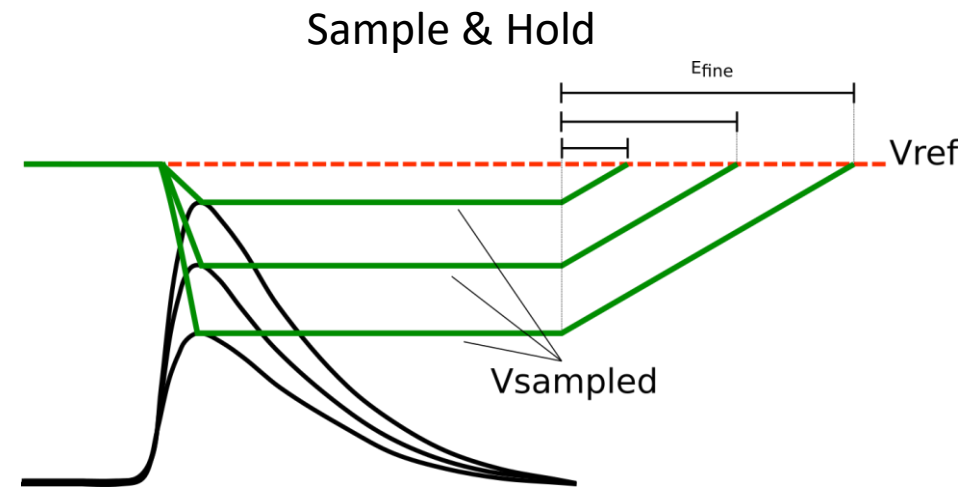
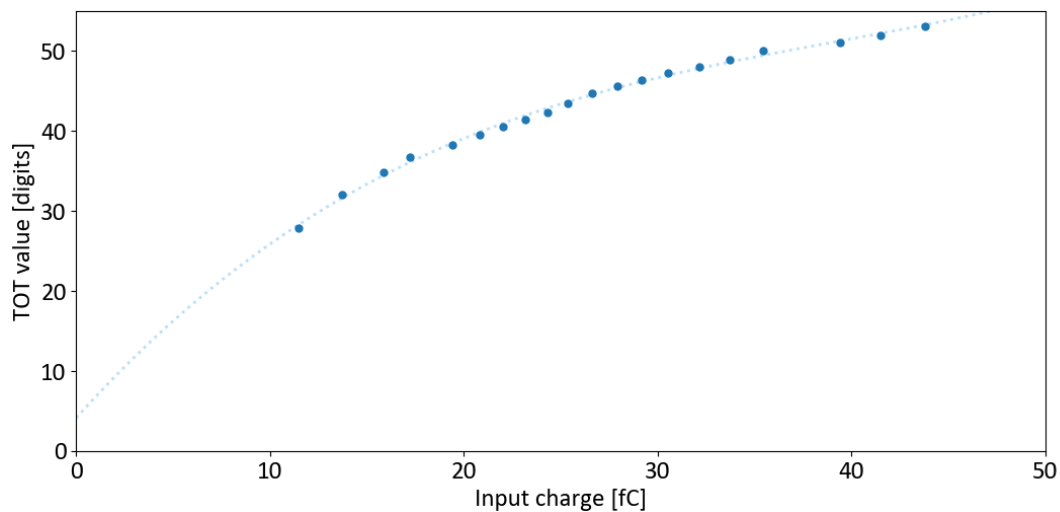
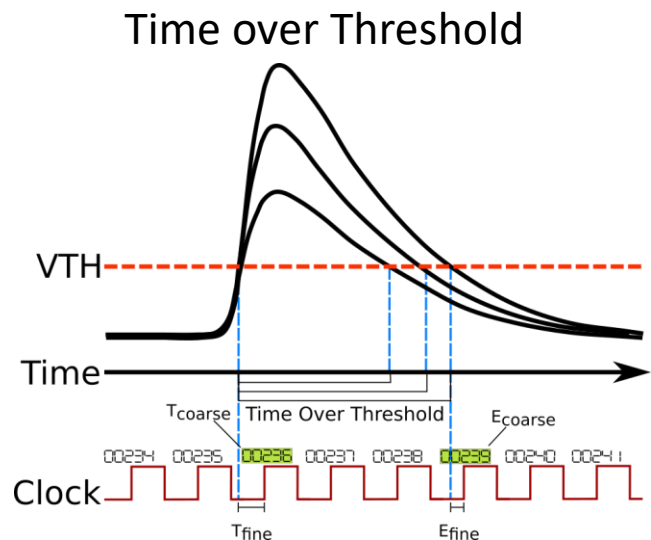
### Fine time

Time to the next clock cycle  
50 ps binning

$$T = Coarse \times 6.25 \text{ ns} - (Fine-min) \times \text{binning}$$

4 TAC per shaper for event de-randomization  
1 Wilkinson ADC per branch

# Charge measurement



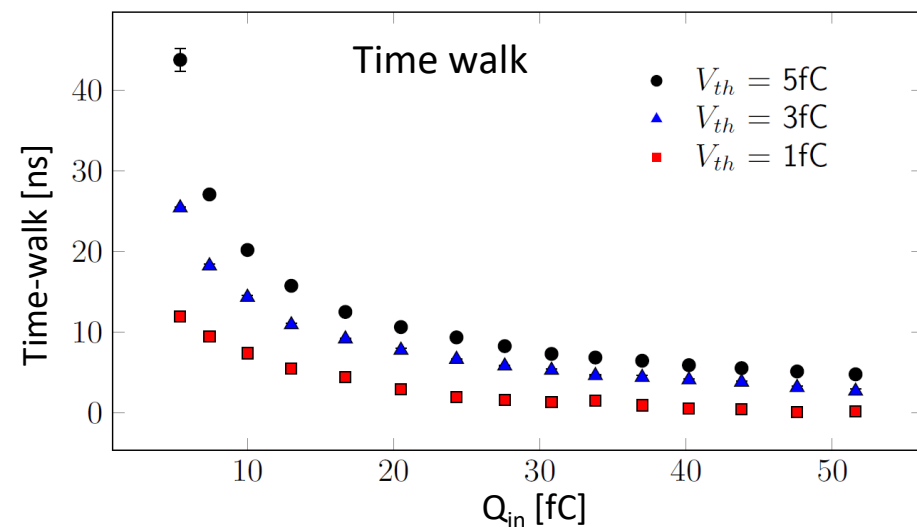
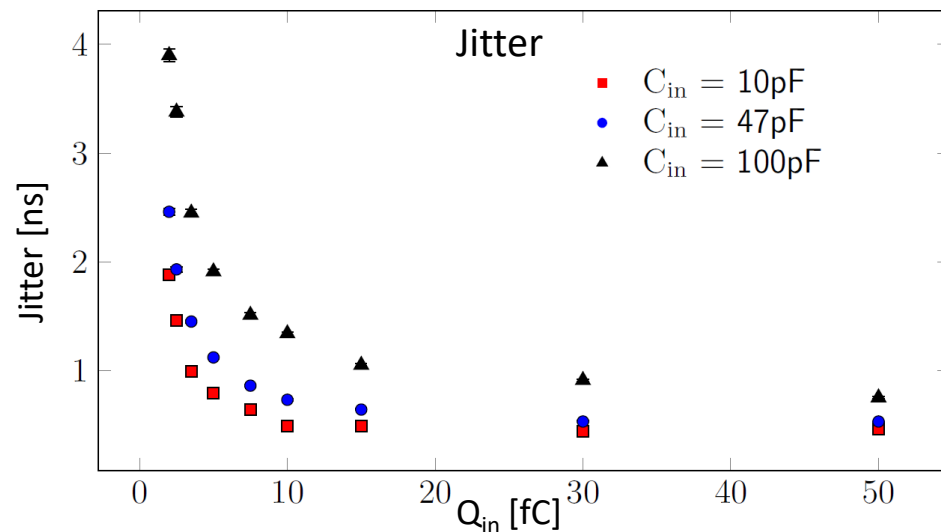
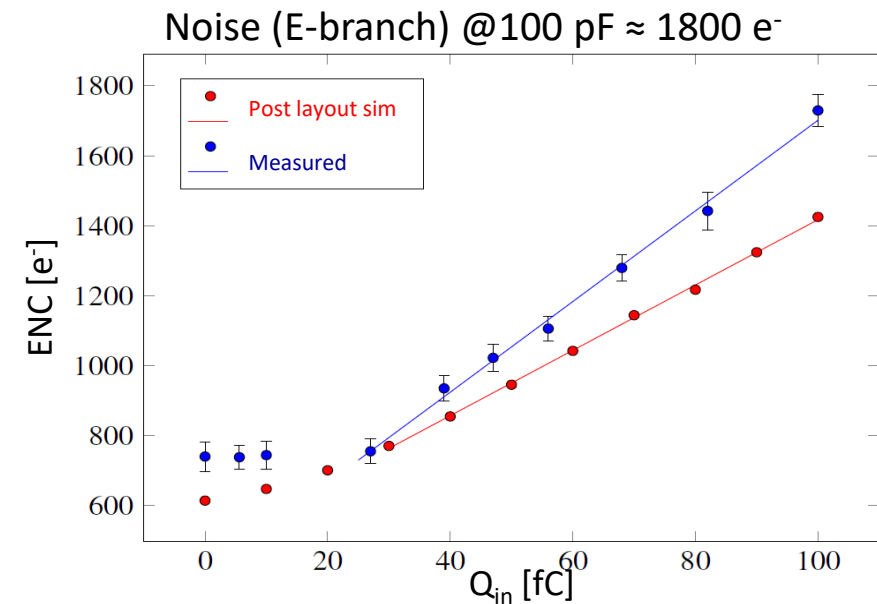
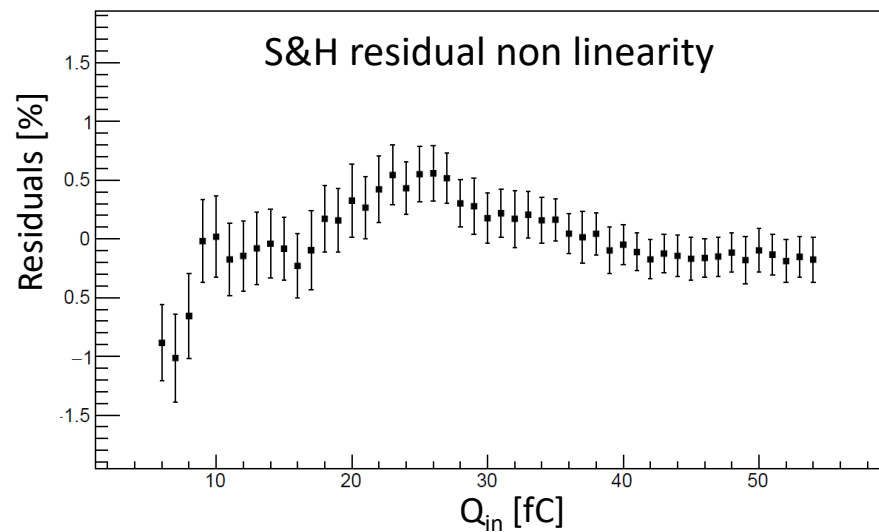
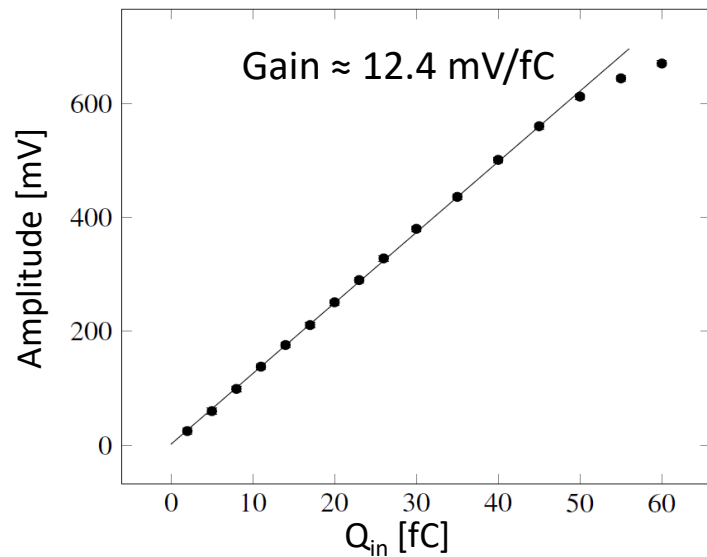
# Digital backend

- Backend inherited from TOPFETv2
- 160-200 MHz system clock
- Full digital output with time and charge information
- 4 TX SDR/DDR LVDS links, 8b/10b encoding
- 10 MHz SPI-like configuration link
- SEU protections

The chip hit rate capabilities were tested and confirmed on silicon

- 100 kHz for a single channel
- 60 kHz per channel when all are firing

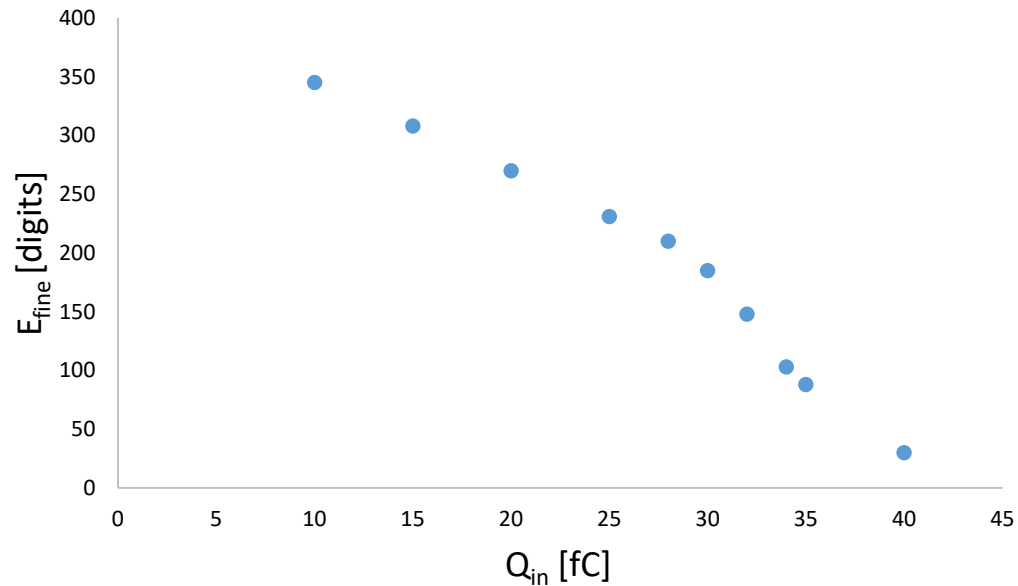
# Performances on silicon



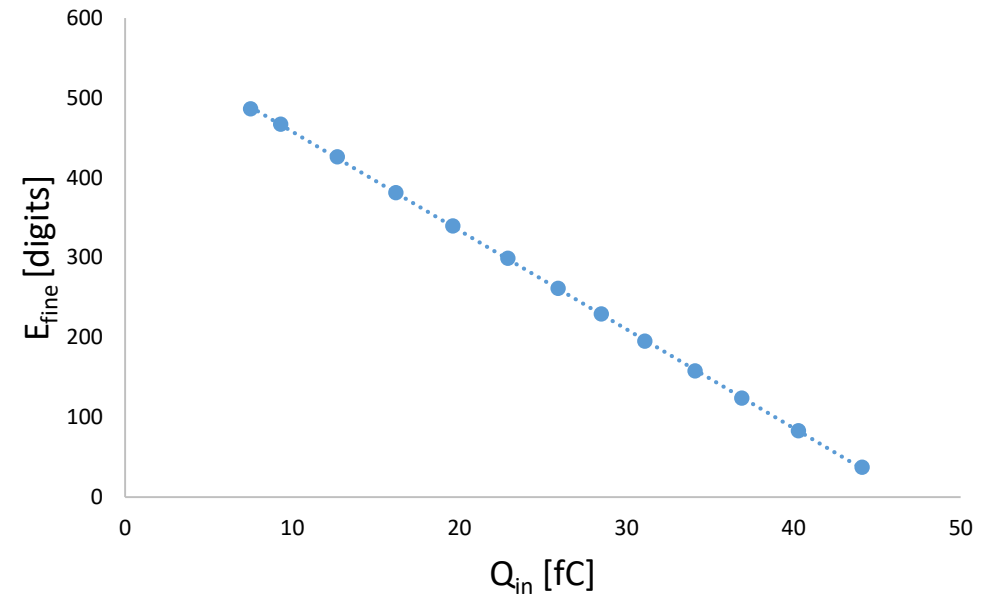
Ref. Fabio Cossio "A mixed-signal ASIC for time and charge measurements with GEM detectors", PhD Thesis (Polito-2019)

# Tuning

S&H with initial configuration



S&H with new configuration



Production yield with our configuration\*

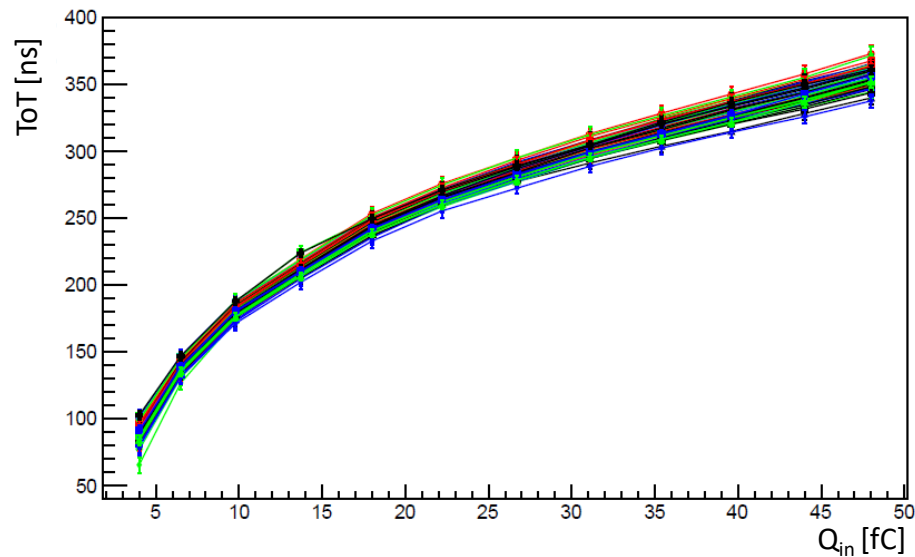
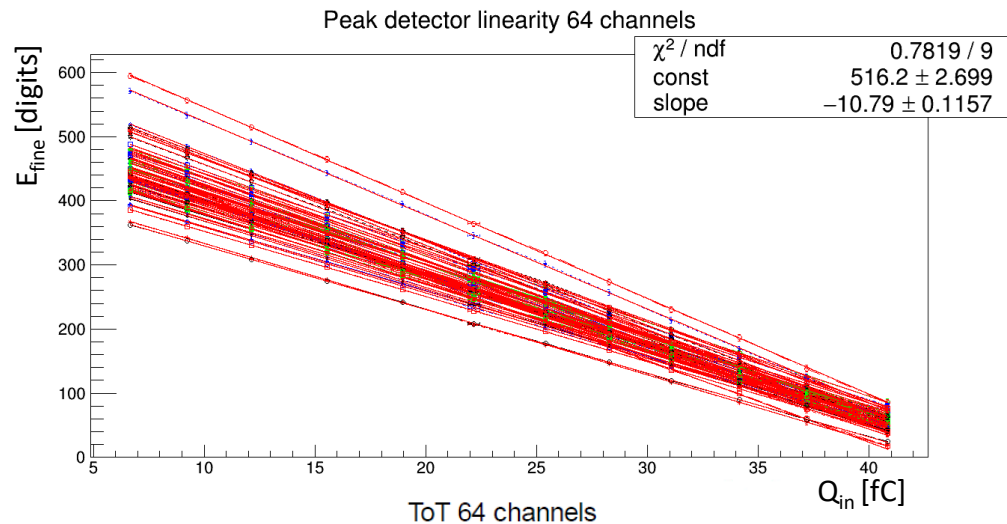
- 98% working chips:
  - 80% meeting our requirements
  - 18% unusable
- 2% totally faulty chips

Requested performance achieved

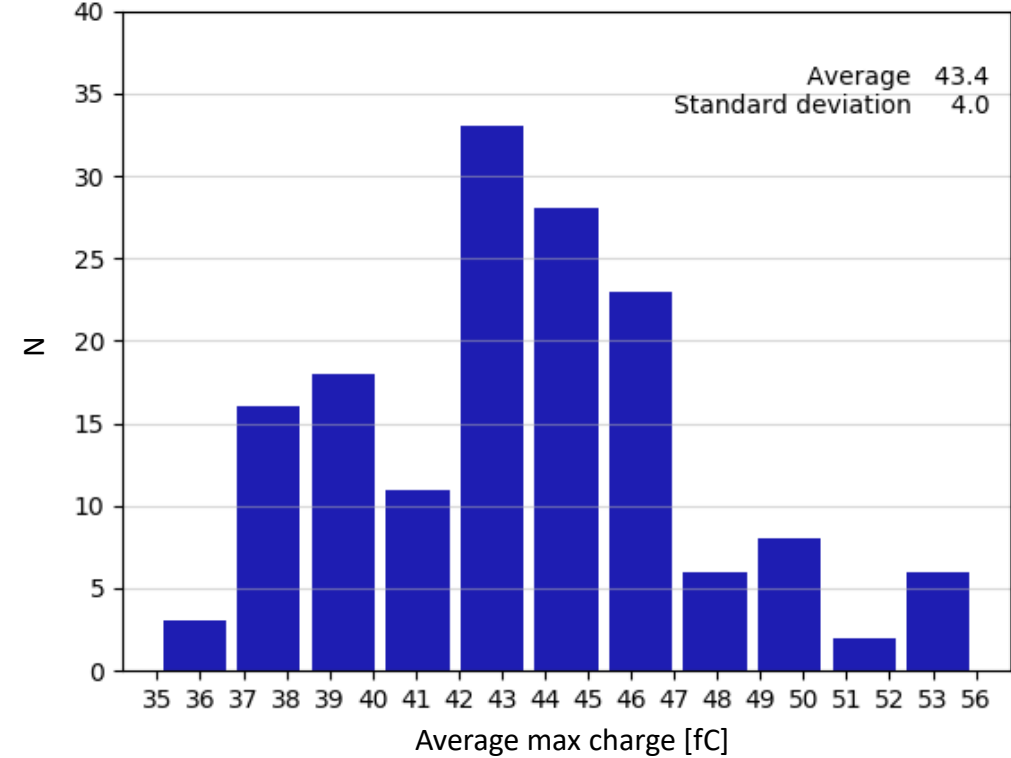
\*Data from the layer 1 production



# Calibration results



S&H range  
Maximum input charge (channel average)

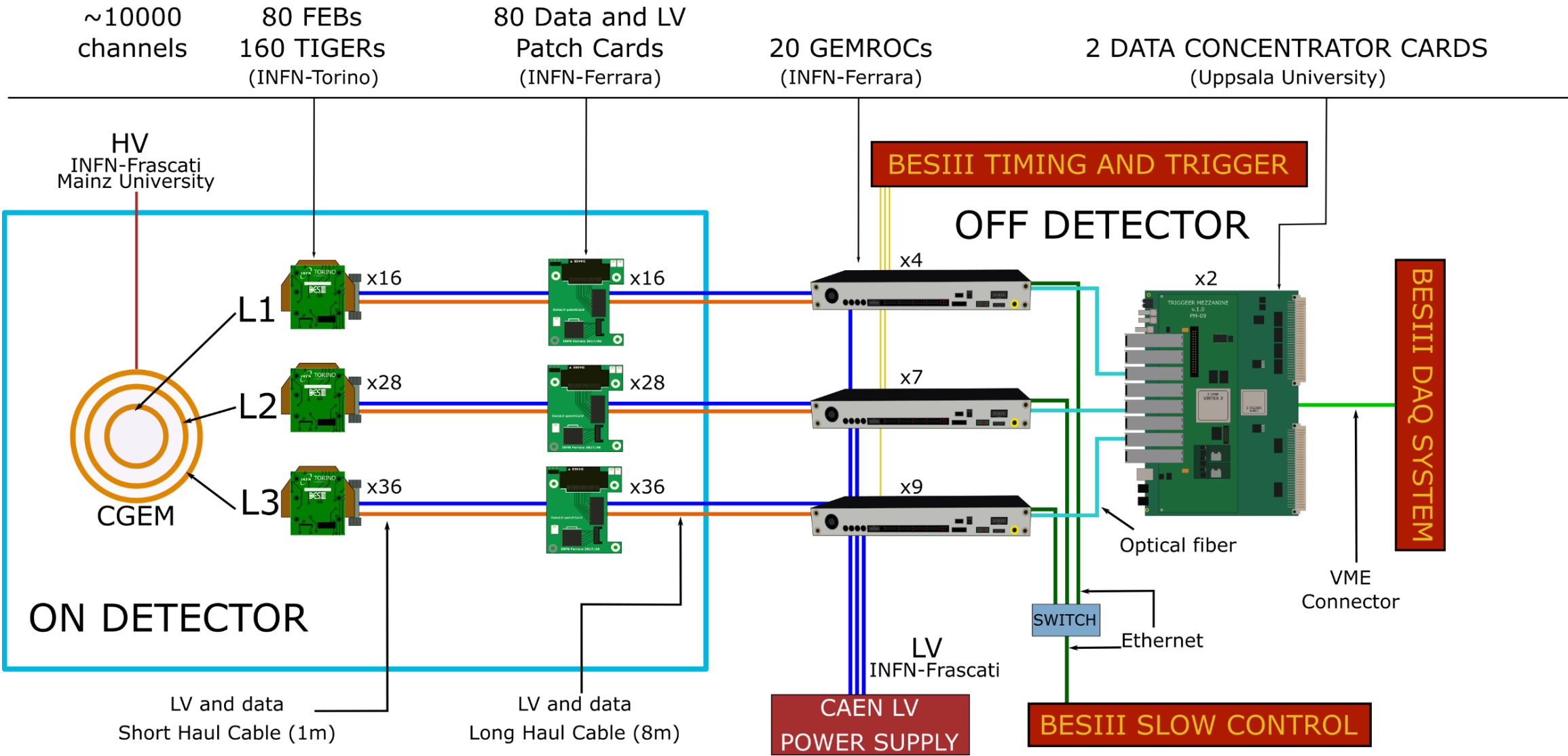


Calibration completed for 10k channels

# Full electronics chain

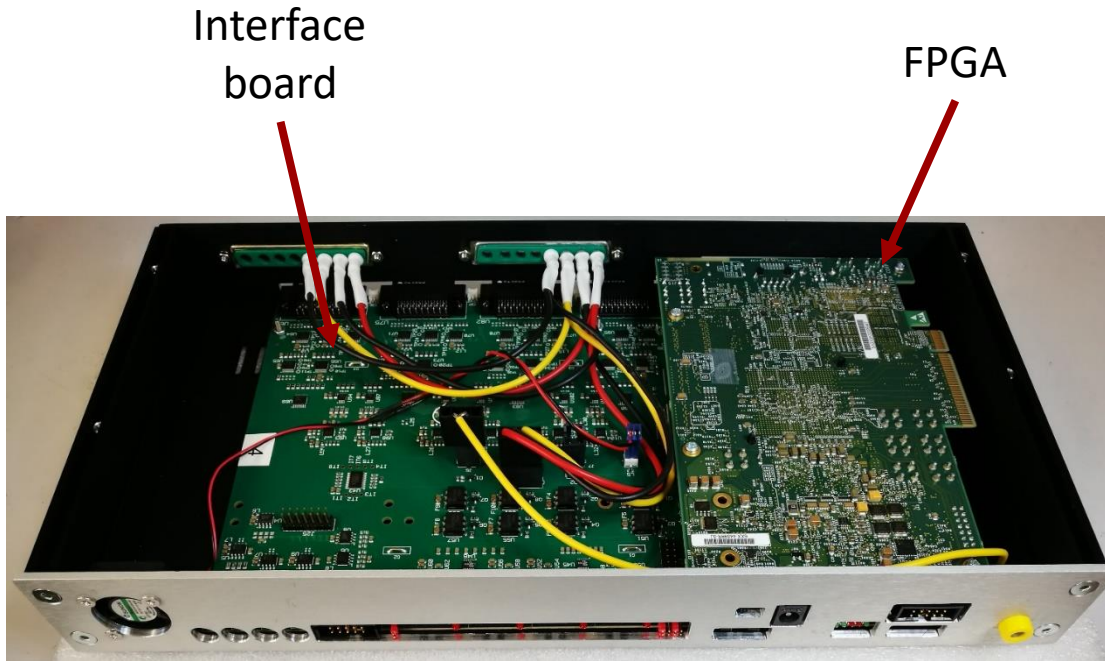


# Electronics read-out



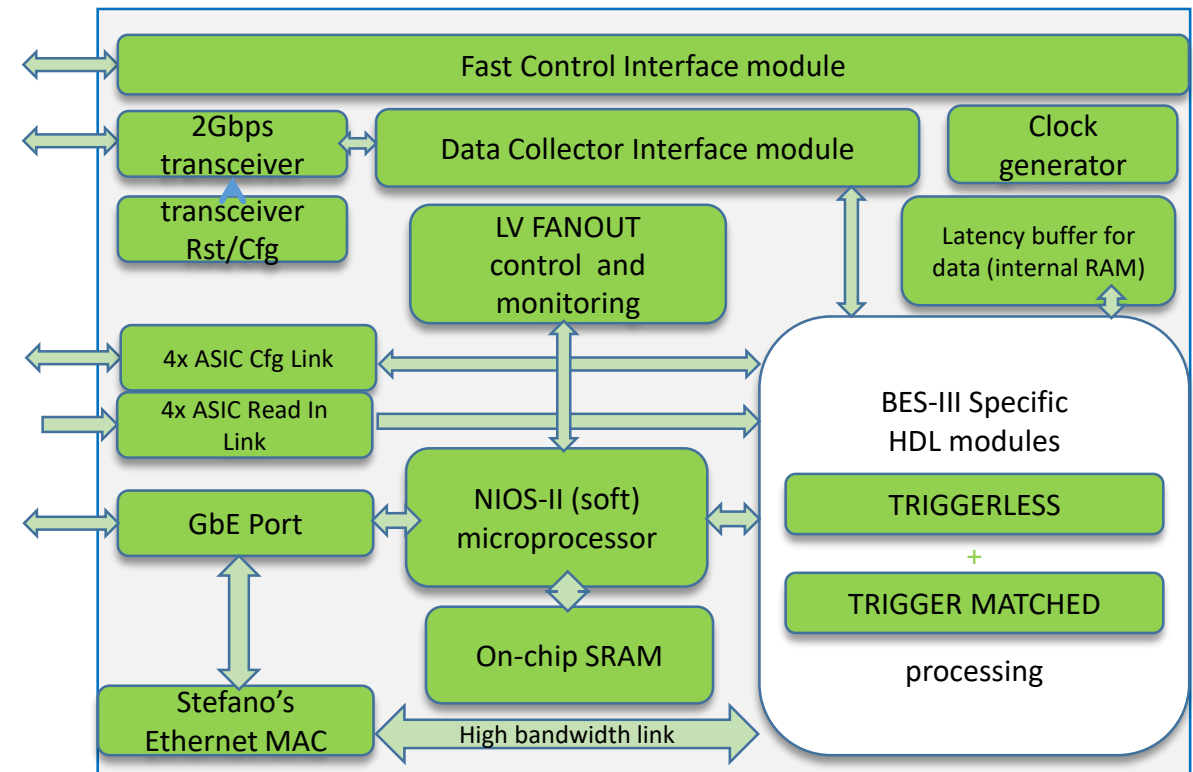
# GEM Read-Out Cards

Designed by Electronic workshop INFN-Ferrara



GEMROC module

## FPGA block scheme

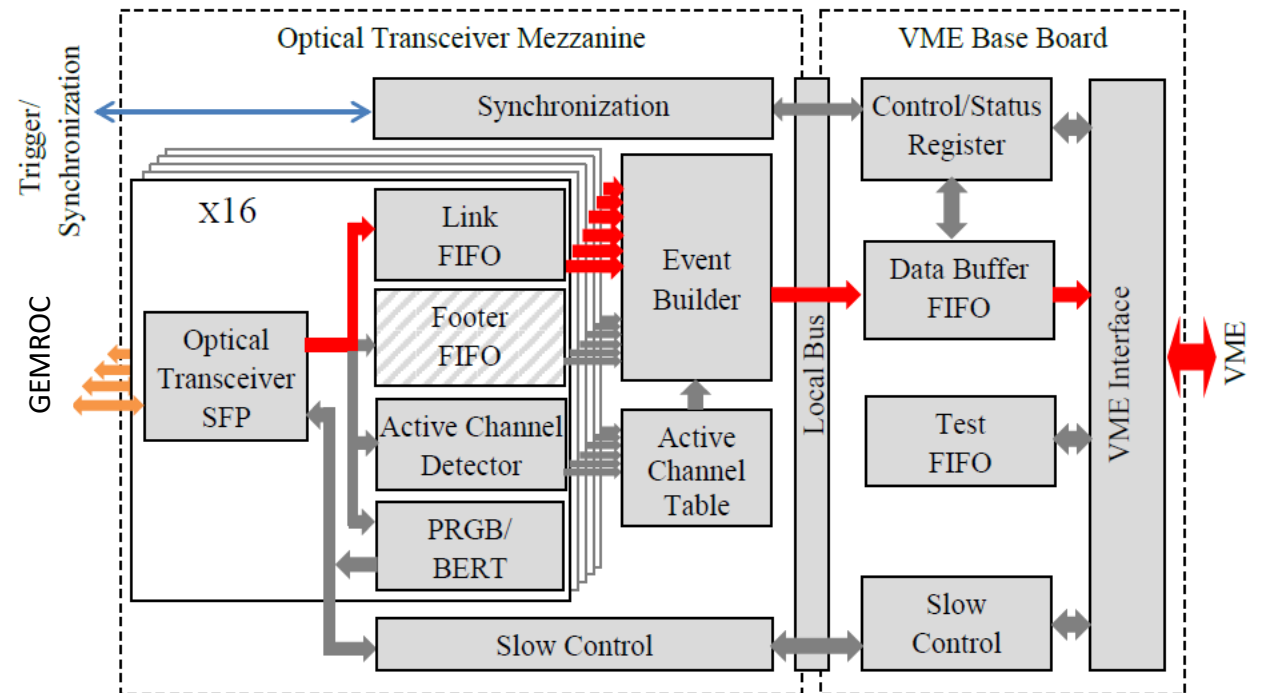
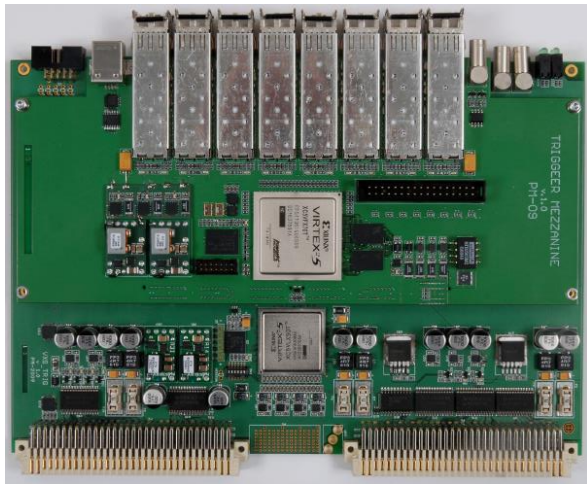


All blocks working, final tests ongoing

# GEM-Data Concentrator

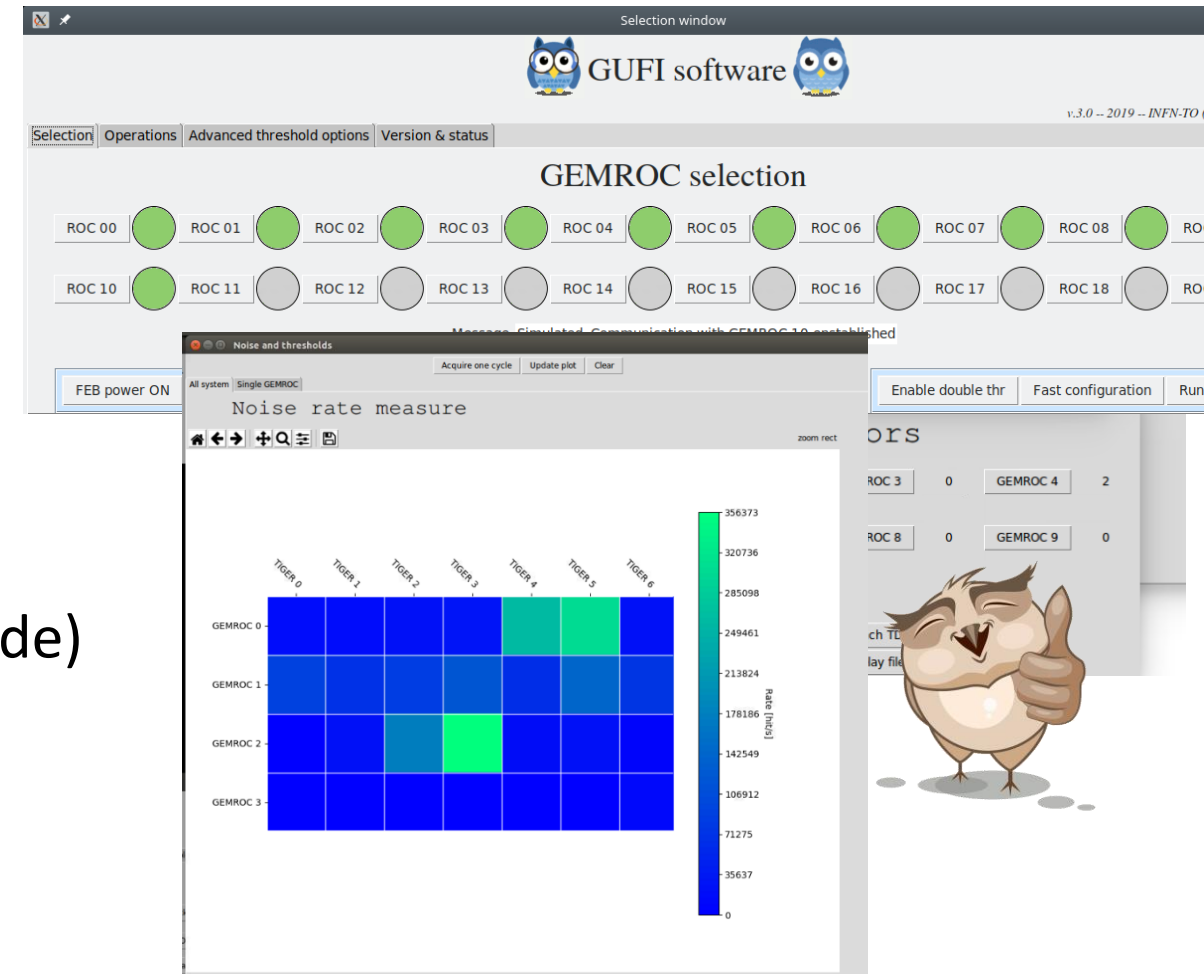
Designed by Uppsala University

- Receives signal from the GEMROCs via optical links
- Build the events
- Optical links @ 2 Gb/s
- Interface trough VME with the BESIII DAQ



# Graphical User Frontend Interface

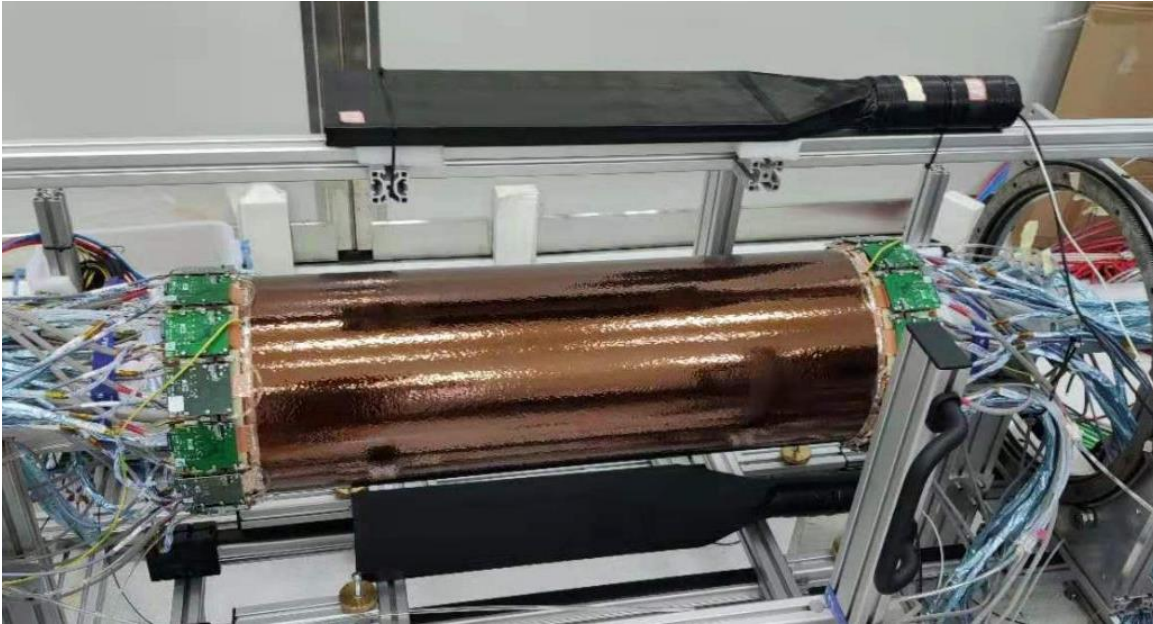
- Interface with GEMROCs and TIGERs
- Configure both the devices
- Manage acquisition
- Online monitoring
- Measure noise rate and other performances
- User friendly interface (user mode/expert mode)





# On detector performances

# Setup status

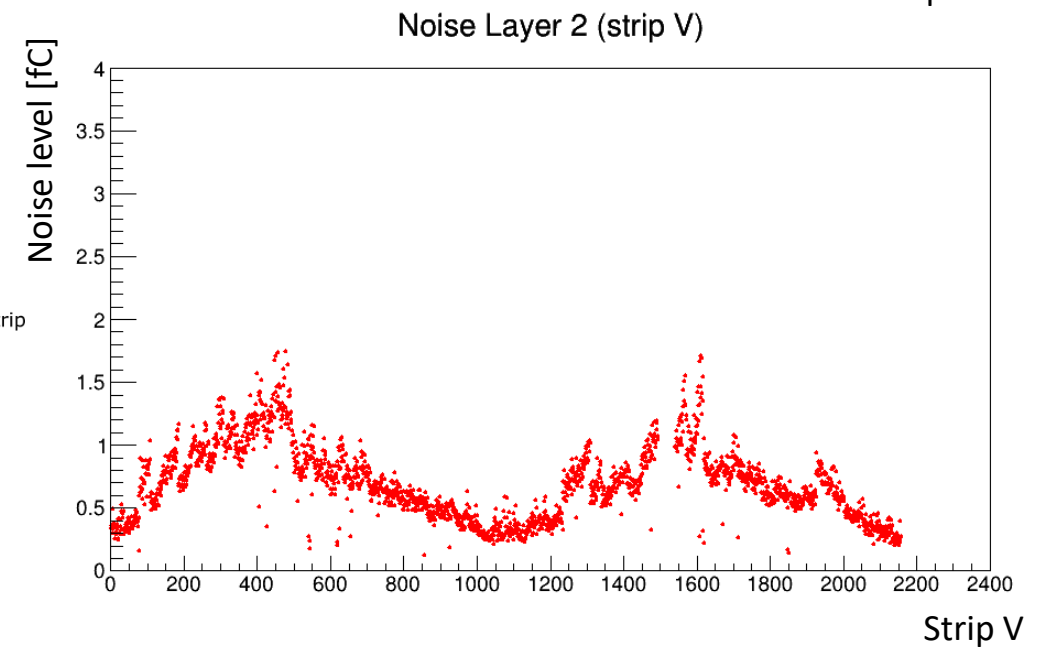
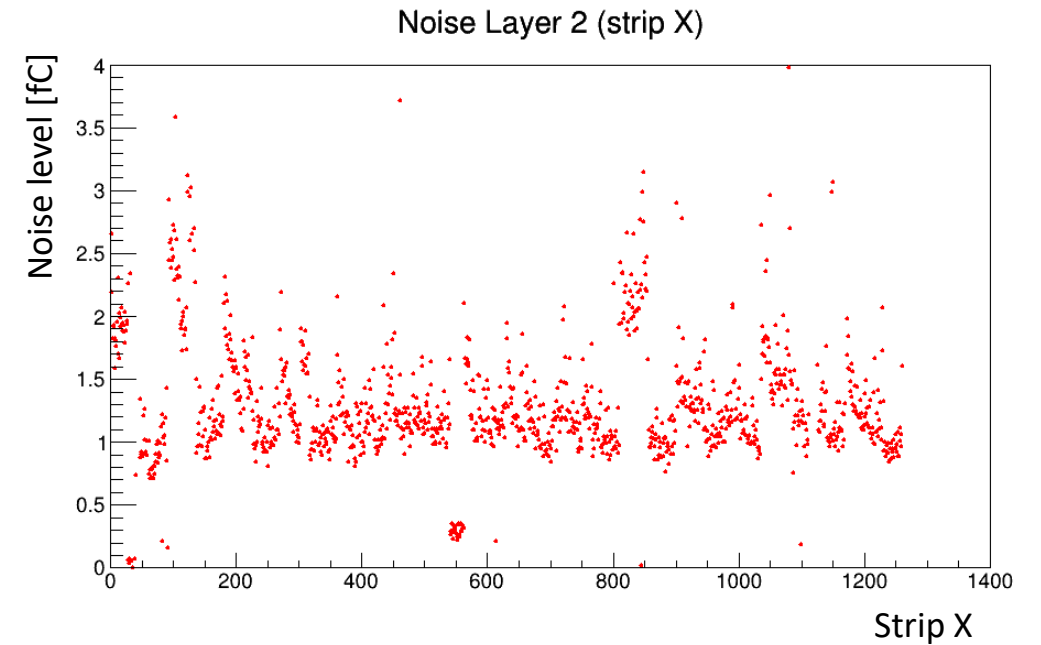
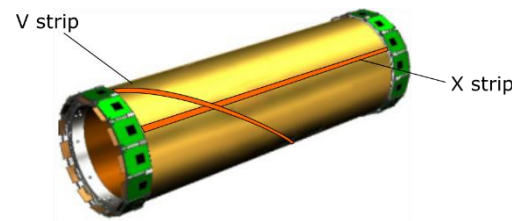
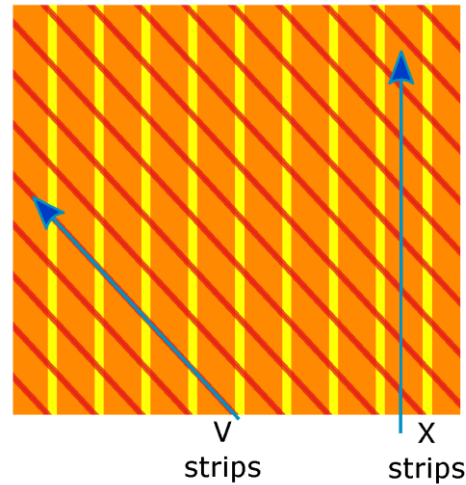
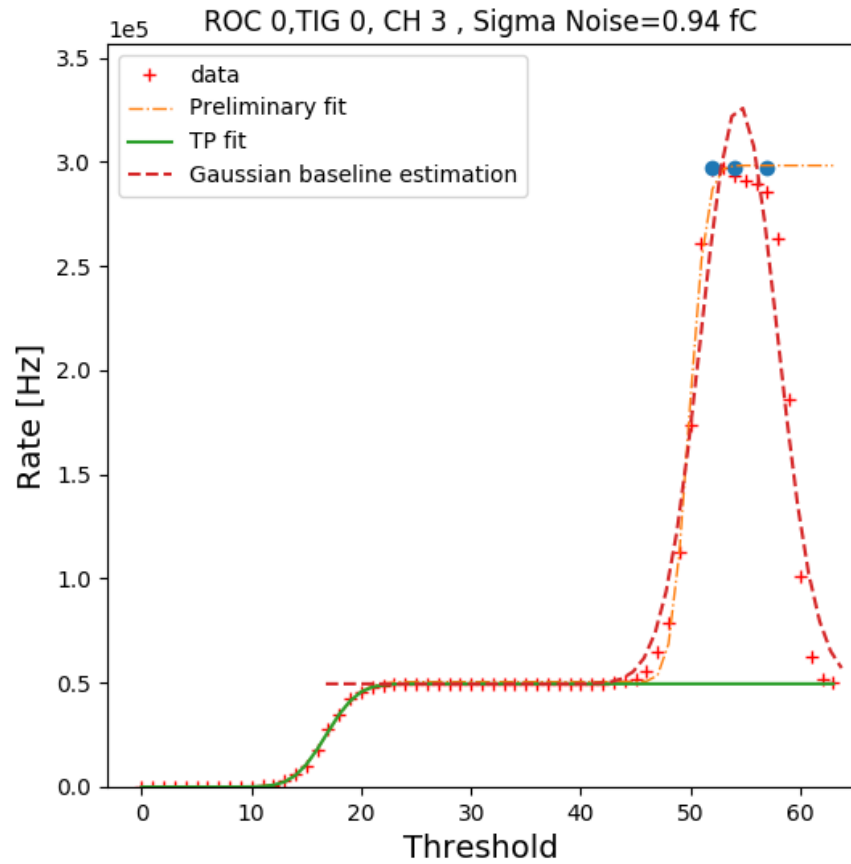


The readout chain integration is ongoing:

- L1 and L2 are instrumented with the ASICs
- Cosmic rays are acquired to evaluate system condition
- The GEMROC firmware is continuously updated to maximize trigger-matching and communication performance and robustness
- Software tools are constantly developed to improve the system understanding and capabilities
- The final layers of the detectors will arrive within 2019



# Noise levels

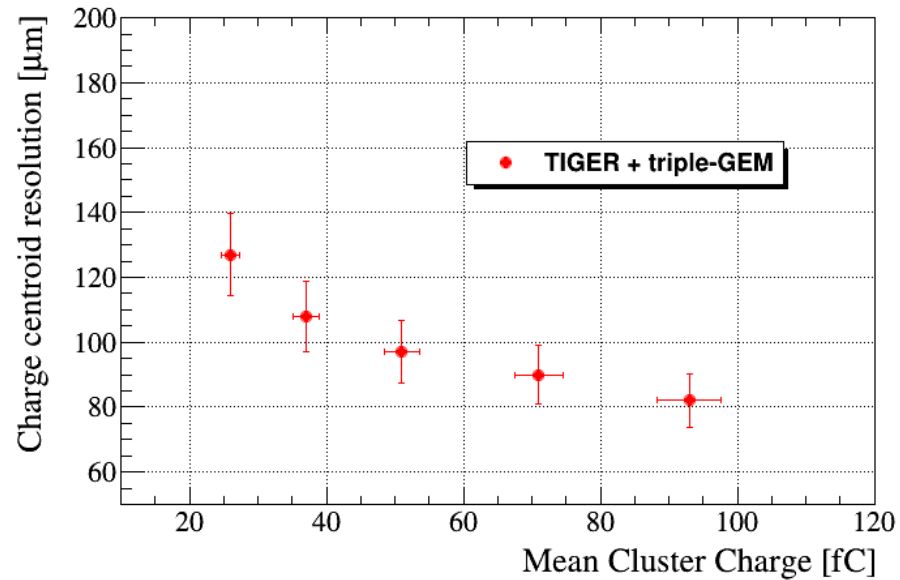


The noise is measured on the system using the internal test pulse and a threshold scan

# Tracking performances

## Planar detector

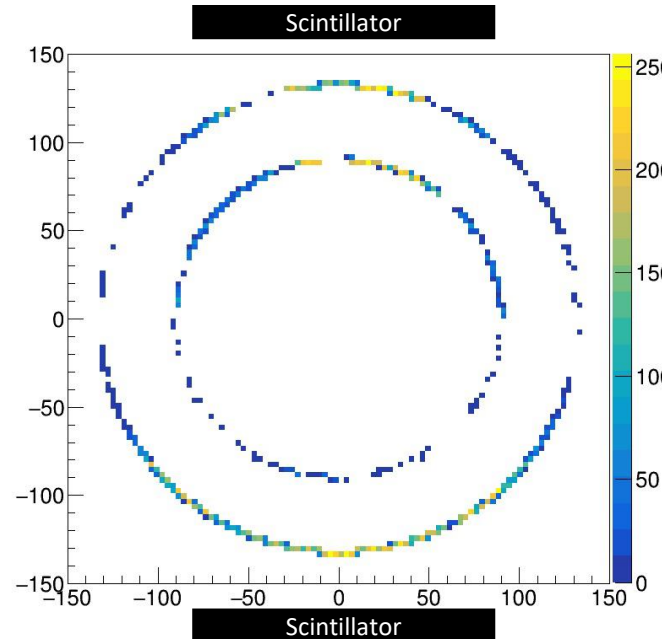
Last year beam test results



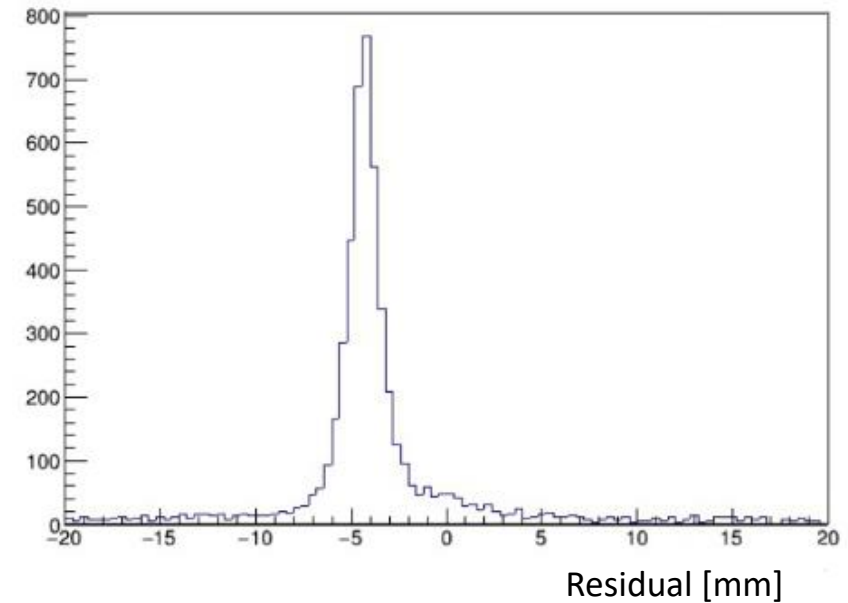
Ref. R. Farinelli "Research and development in cylindrical triple-GEM detector with  $\mu\text{TPC}$  readout for the BESIII experiment", PhD Thesis (UniFe-2019)

## Cylindrical detector

Detector hit rate



Residual distribution (X strips)



# Results

- All the parts are tested and ready to be installed, 2 layers are already instrumented
- The system is stable and reliable
- We are able to produce data with good quality, useful for the tracking software final tuning and the detector performance evaluation

# Next steps

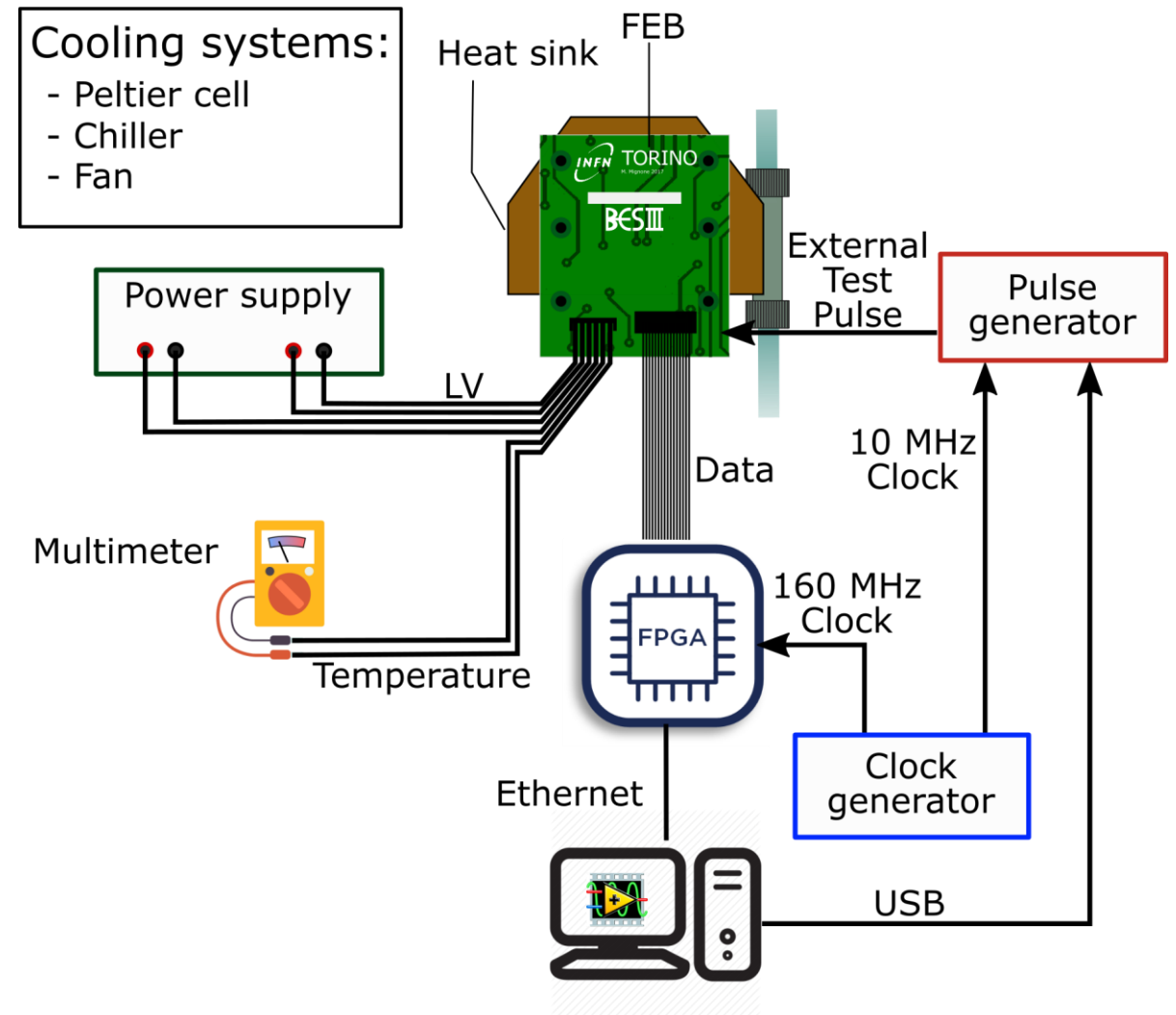
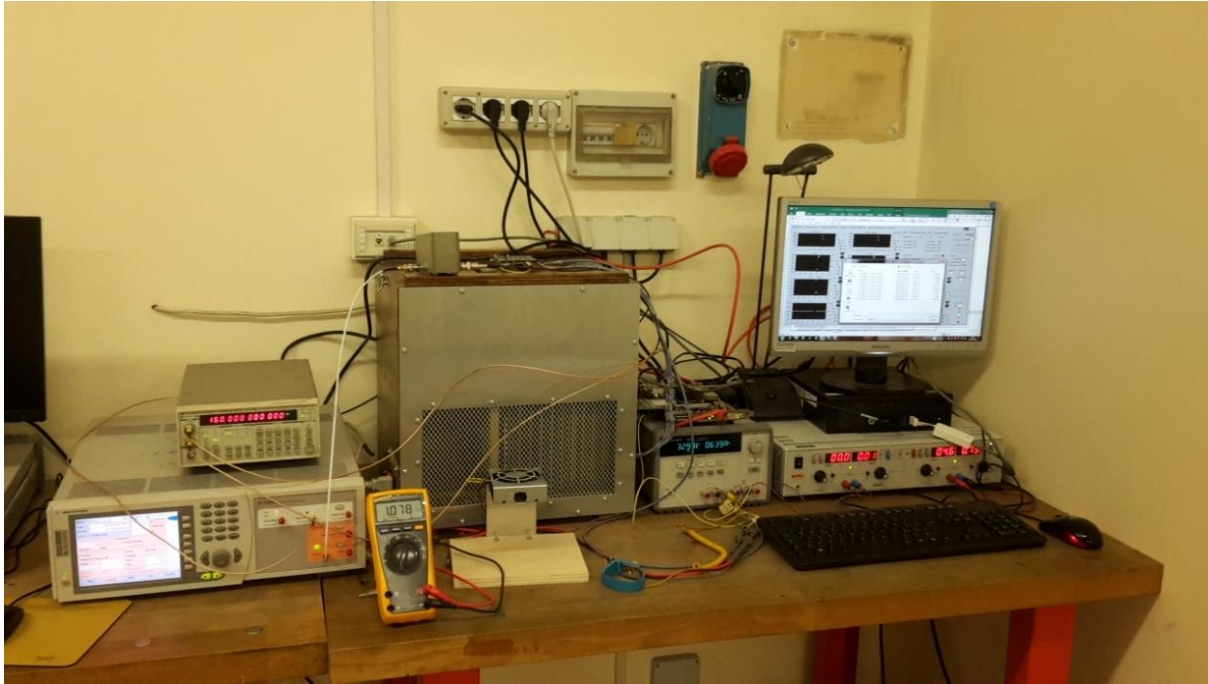
- Complete the integration with the full detector
- Equalize and lower the thresholds
- Optimize the grounding in order to reduce the noise
- Compatibility tests with the MDC are ongoing
- Tracking and efficiency results with the current setup will be presented to the BESIII collaboration soon
- Installation within the end of next year



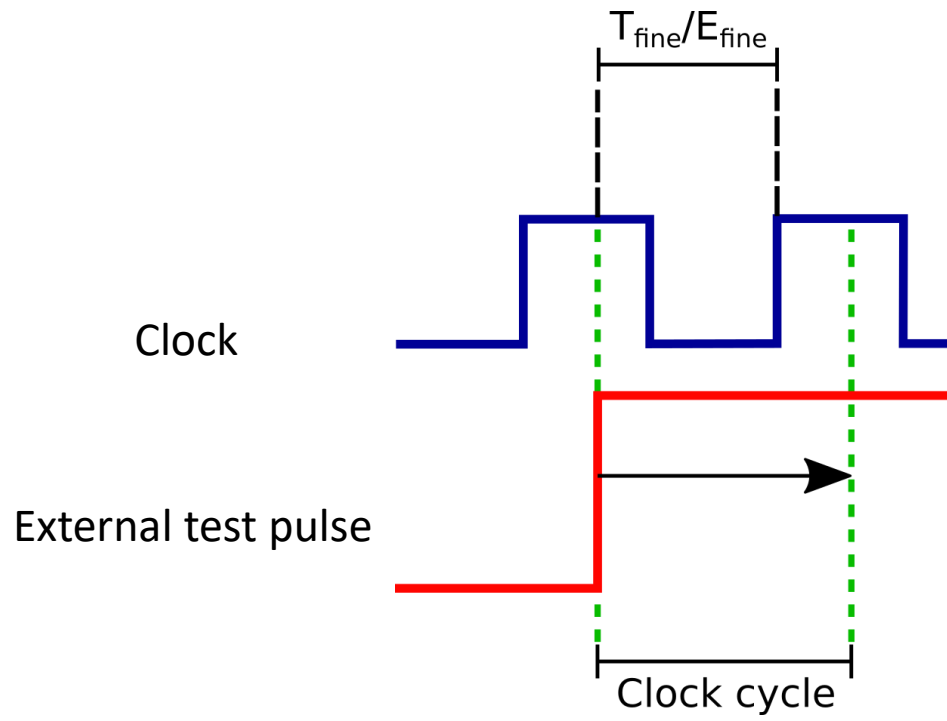
# THANK YOU FOR YOUR ATTENTION

# BACKUP SLIDES

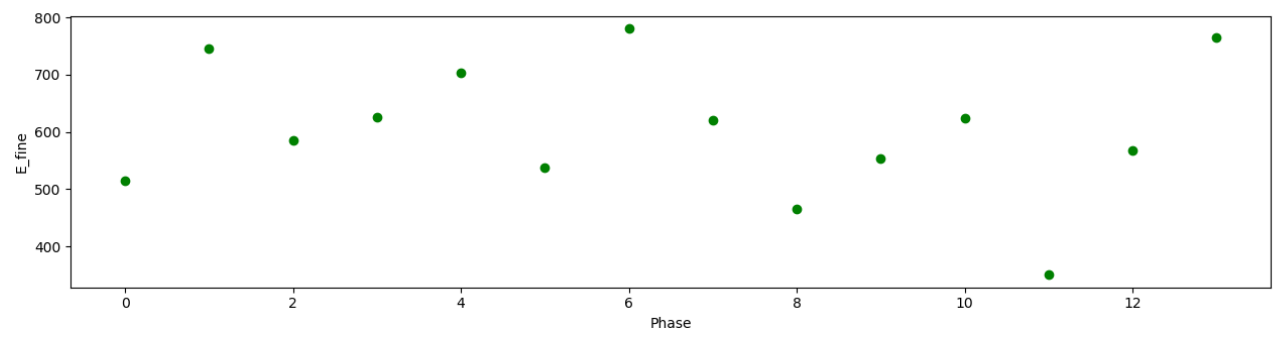
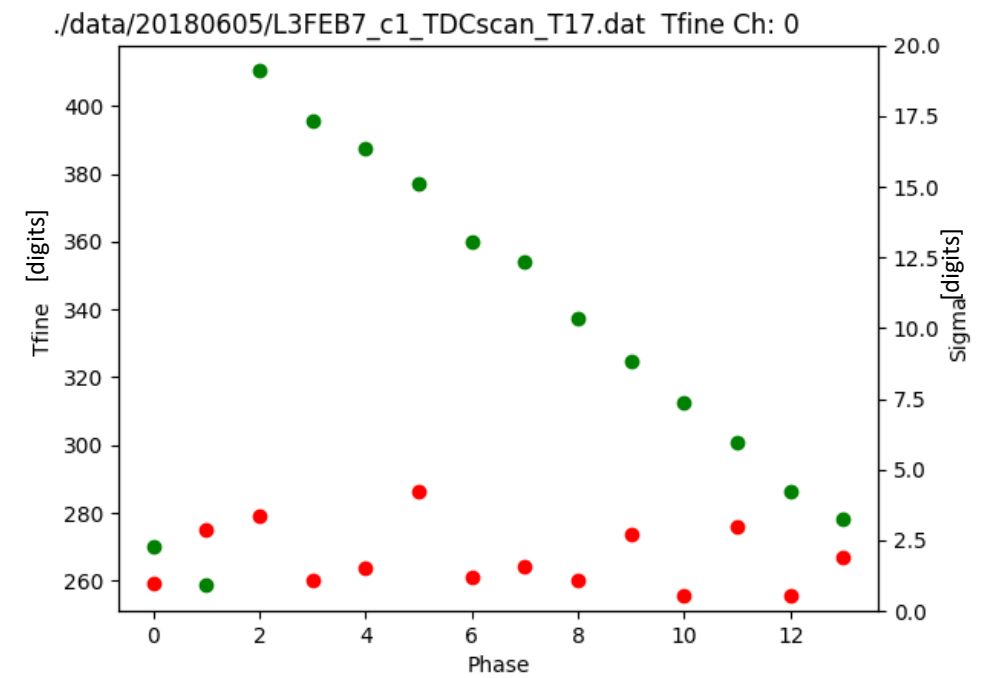
# Test and calibration setup



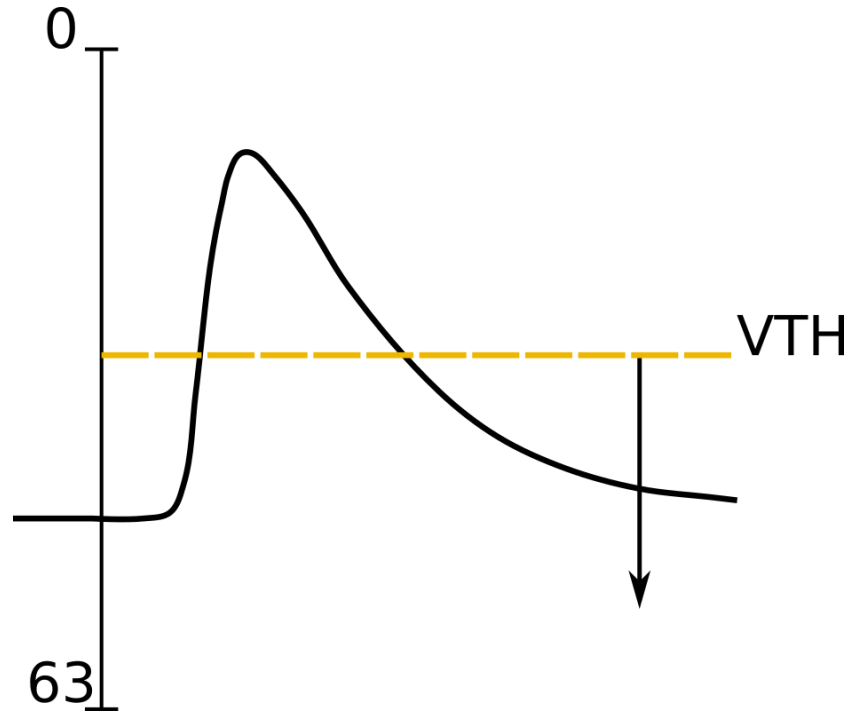
# TDC scan



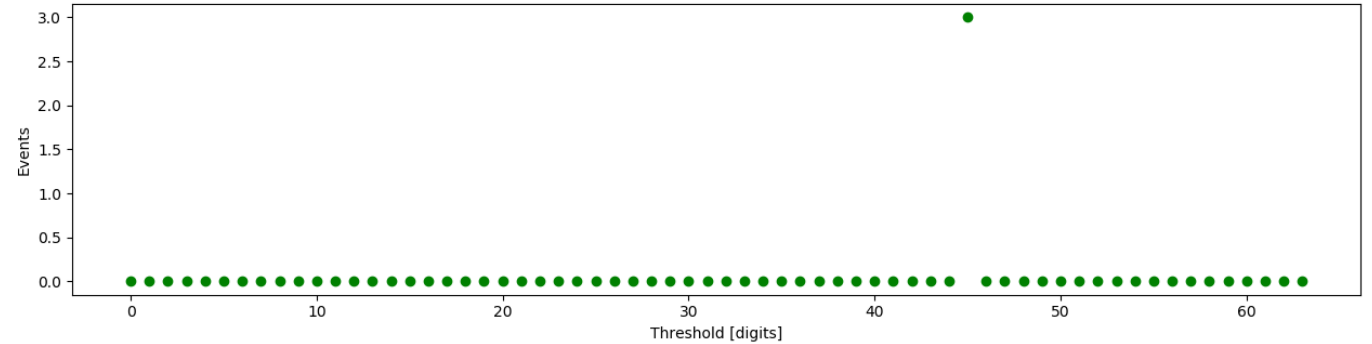
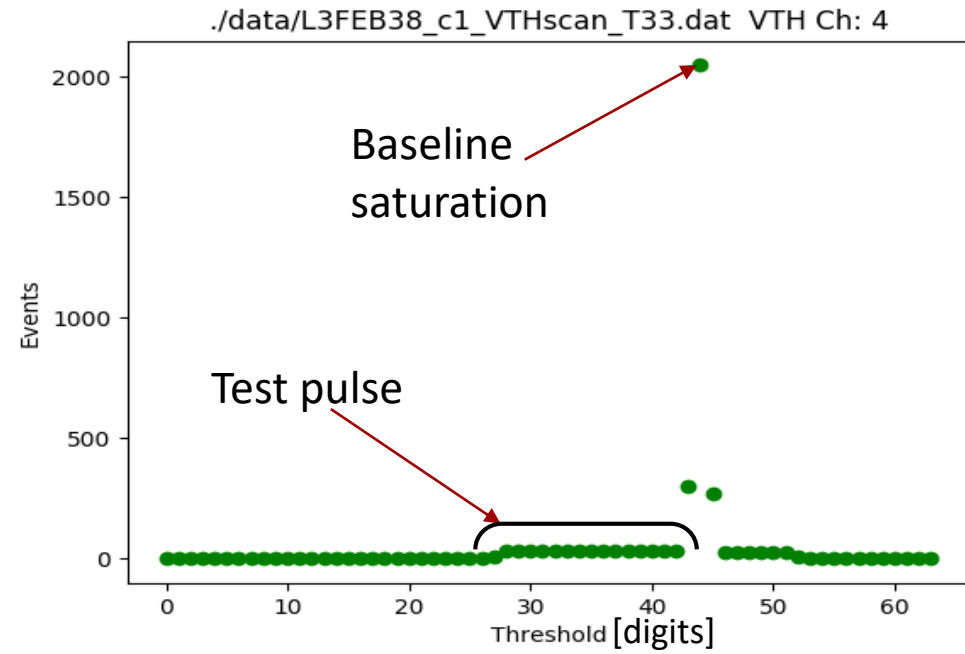
Sweep test pulse phase, along one clock cycle, to scan TDC response



# Threshold scan

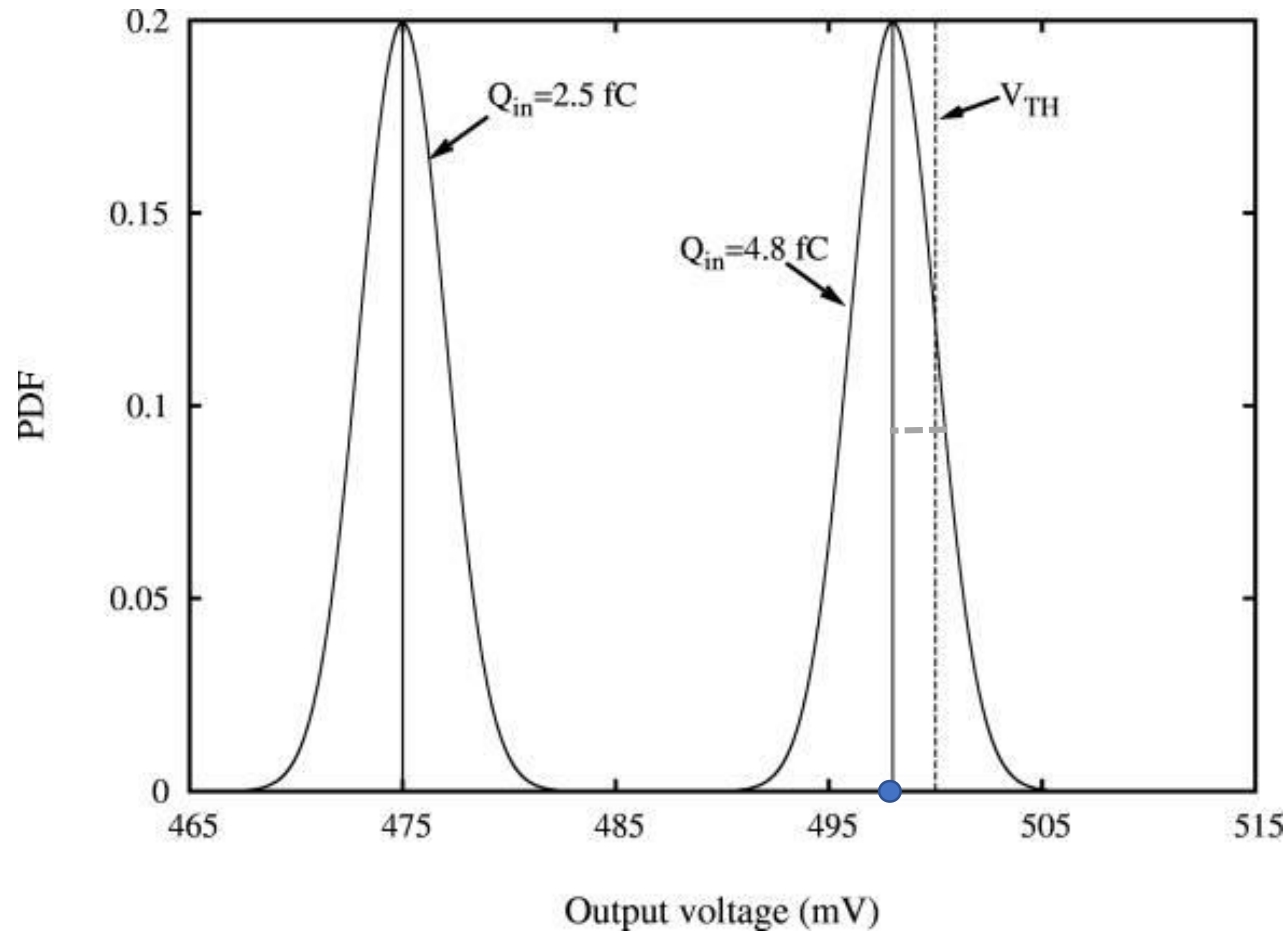


Sweep threshold value to test front end behavior and measure baseline and noise

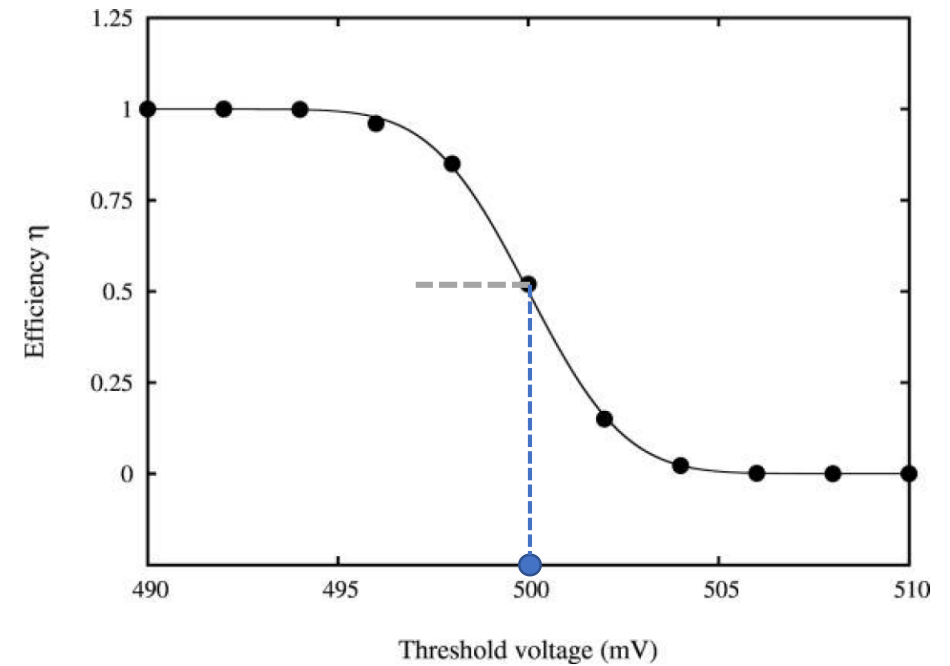




# S-CURVE FITTING



$$\eta = \frac{\text{Number of answers}}{\text{Number of sent signals}}$$

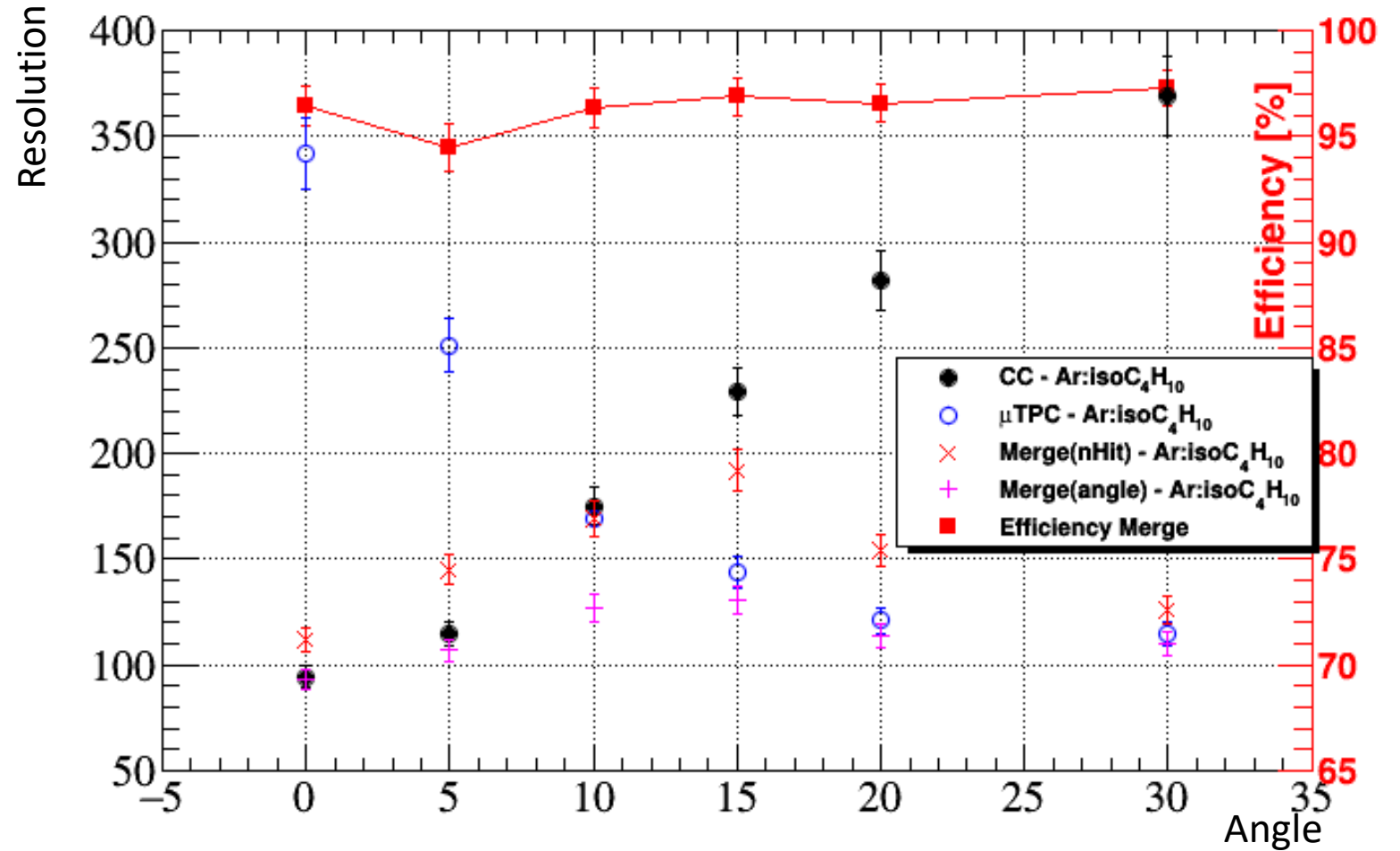


$$\eta(Q) = \frac{1}{2} \left[ \text{erf} \left( \frac{Q - \mu}{\sqrt{2}\sigma} \right) + 1 \right] \quad (1.45)$$

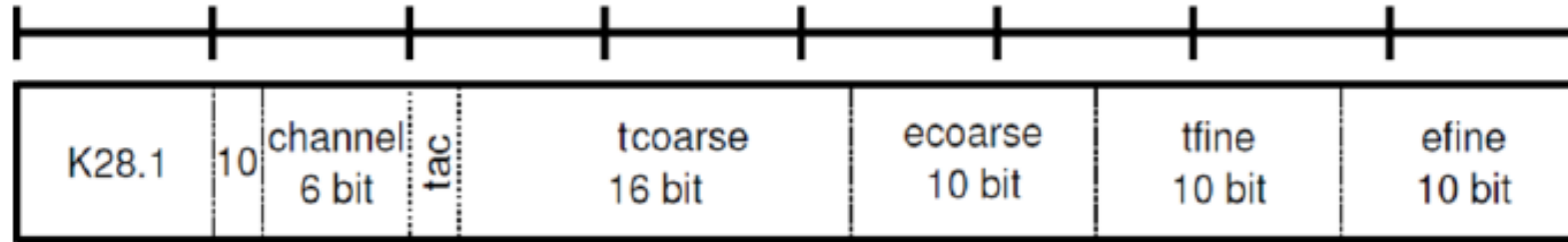
Reference: A. Rivetti CMOS Front-End Electronics for Radiation Sensors

# Merging

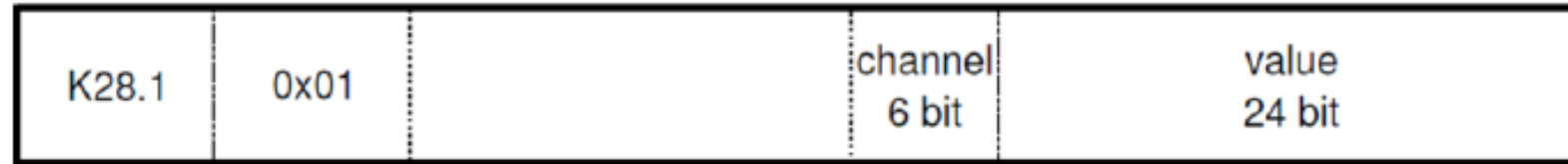
Two different merging procedures,  
integrated with iterative algorithm



# Transmitted words



Event word



Count word



Framing word

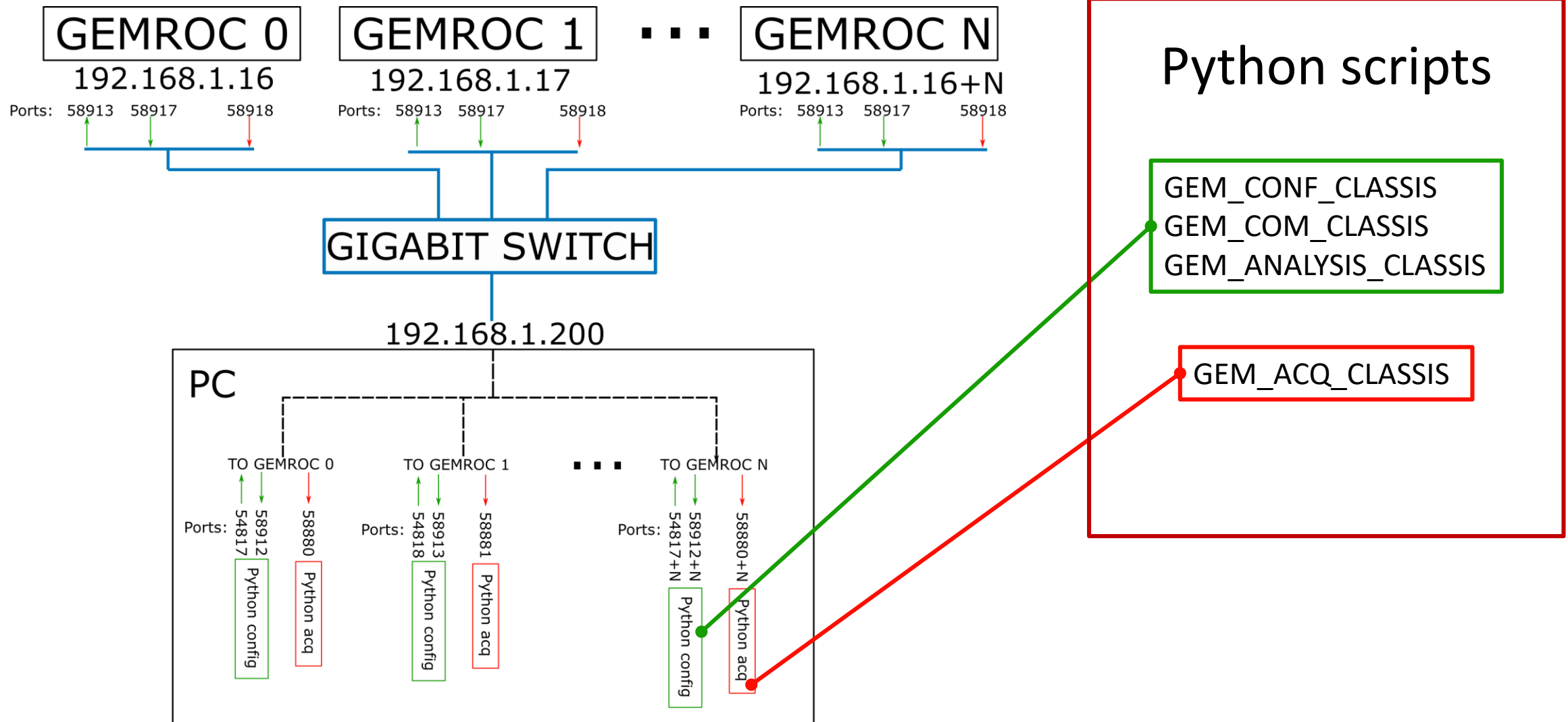
# Calibration

- Calibration of both S&H and ToT needed to compensate offset between the 64 channels
- The number of chips made mandatory to implement a fast calibration system

	Channel number	
0	545.997066096	-10.6147279072
1	526.211169351	-11.7170504502
2	580.351899351	-11.6062163376
3	544.412377277	-11.042095105
4	556.244031582	-10.633545443
5	556.268678257	-10.9560682097
6	530.88892553	-10.3052071816
7	558.532758103	-11.0038186379
8	546.298270949	-10.6455693999
9	46	'88' 9.25' '3265

Look up table sample

# Network architecture



# UDP buffers settings

1. `#!/bin/bash`
2. `sysctl -w net.core.netdev_max_backlog=64000`
3. `sysctl -w net.core.rmem_max=1677721600`
4. `sysctl -w net.core.wmem_max=1677721600`
5. `sysctl -w net.core.rmem_default=1677721600`
6. `sysctl -w net.core.wmem_default=1677721600`
7. `ifconfig enp2s0f1 txqueuelen 100000`
8. `ethtool -G enp2s0f1 rx 2047`

- Line 1 makes the script executable.
- Line 2 changes the backlog size. The backlog is a buffer where the incoming data from the interface card are stacked waiting for the CPU to read the content of the packets, recognize the protocol used and route the packets into the correct buffer, there is one backlog buffer for each core.
- Lines from 3 to 6 increase the size of the buffers allocated for each socket created by the Python script for both incoming and outgoing data.
- Line 7 increases the length of the transmission queue at the kernel level. In this stack, the data incoming from the socket and going to the interface card are stored.
- Line 8 increases the ring memory allocated on the interface card for the reception buffer.

# Procedures

## Chip validation (done at $T_{amb}$ and cooled)

- **TDC scan** → functioning of the ASIC TAC and digital back-end
- Fast **Vth scan** → front-end response

## Chip calibration

- **TDC scan** → calibration of fine time
- **Vth scan** → thresholds equalization
- **Internal Test Pulse calibration** using external pulse generator on one channel
- Test and **calibrate 64** channels for both ToT and S&H with internal test pulse
- **Python script** to generate calibration references (*FEB id, chip id, channel id, ADC counts vs  $Q_{in}$* )